

PIC16C62X

EPROM-Based 8-Bit CMOS Microcontroller

Devices included in this data sheet:

Referred to collectively as PIC16C62X.

- PIC16C620
- PIC16C620A
- PIC16C621
- PIC16C621A
- PIC16C622
- PIC16C622A
- PIC16CR620A

High Performance RISC CPU:

- · Only 35 instructions to learn
- All single-cycle instructions (200 ns), except for program branches which are two-cycle
- Operating speed:
 - DC 20 MHz clock input
 - DC 200 ns instruction cycle

Device	Program Memory	Data Memory
PIC16C620	512	80
PIC16C620A	512	96
PIC16CR620A	512	96
PIC16C621	1K	80
PIC16C621A	1K	96
PIC16C622	2K	128
PIC16C622A	2K	128

- · Interrupt capability
- 16 special function hardware registers
- 8-level deep hardware stack
- · Direct, Indirect and Relative addressing modes

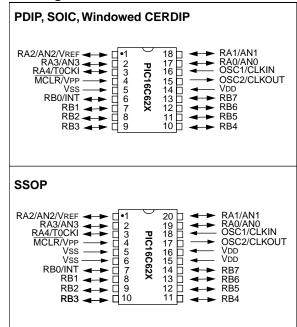
Peripheral Features:

- 13 I/O pins with individual direction control
- · High current sink/source for direct LED drive
- Analog comparator module with:
 - Two analog comparators
 - Programmable on-chip voltage reference (VREF) module
 - Programmable input multiplexing from device inputs and internal voltage reference
 - Comparator outputs can be output signals
- Timer0: 8-bit timer/counter with 8-bit programmable prescaler

Special Microcontroller Features:

- · Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- · Brown-out Reset
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation

Pin Diagrams



Special Microcontroller Features (cont'd)

- Programmable code protection
- · Power saving SLEEP mode
- Selectable oscillator options
- Serial in-circuit programming (via two pins)
- Four user programmable ID locations

CMOS Technology:

- Low-power, high-speed CMOS EPROM technology
- Fully static design
- · Wide operating voltage range
 - PIC16C62X 2.5V to 6.0V
 - PIC16C62XA 2.5V to 5.5V
 - PIC16CR620A 2.0V to 5.5V
- Commercial, industrial and extended temperature range
- Low power consumption
 - < 2.0 mA @ 5.0V, 4.0 MHz
 - 15 μA typical @ 3.0V, 32 kHz
 - < 1.0 μA typical standby current @ 3.0V

PIC16C62X

Device Differences

Device	Voltage Range	Oscillator	Process Technology (Microns)		
PIC16C620	2.5 - 6.0	See Note 1	0.9		
PIC16C621	2.5 - 6.0	See Note 1	0.9		
PIC16C622	2.5 - 6.0	See Note 1	0.9		
PIC16C620A	2.5 - 5.5	See Note 1	0.7		
PIC16CR620A	2.0 - 5.5	See Note 1	0.7		
PIC16C621A	2.5 - 5.5	See Note 1	0.7		
PIC16C622A	2.5 - 5.5	See Note 1 0.7			

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

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Errata

An errata sheet may exist for current devices, describing minor operational differences (from the data sheet) and recommended workarounds. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

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Corrections to this Data Sheet

We constantly strive to improve the quality of all our products and documentation. We have spent a great deal of time to ensure that this document is correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error, please:

- · Fill out and mail in the reader response form in the back of this data sheet.
- E-mail us at webmaster@microchip.com.

We appreciate your assistance in making this a better document.

PIC16C62X

NOTES:

1.0 GENERAL DESCRIPTION

The PIC16C62X are 18 and 20 Pin ROM/EPROM-based members of the versatile PICmicro $^{\text{TM}}$ family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers.

All PICmicro™ microcontrollers employ an advanced RISC architecture. The PIC16C62X have enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single-cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16C62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16C620A, PIC16C621A and PIC16CR620A have 96 bytes of RAM. The PIC16C622(A) has 128 bytes of RAM. Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16C62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16C62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers power savings. The user can wake up the chip from SLEEP through several external and internal interrupts and reset.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock- up.

A UV-erasable CERDIP-packaged version is ideal for code development while the cost-effective One-Time Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16C62X mid-range microcontroller families.

A simplified block diagram of the PIC16C62X is shown in Figure 3-1.

The PIC16C62X series fit perfectly in applications ranging from battery chargers to low-power remote sensors. The EPROM technology makes customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high-performance, ease of use and I/O flexibility make the PIC16C62X very versatile.

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to PIC16C62X family of devices (Appendix B). The PIC16C62X family fills the niche for users wanting to migrate up from the PIC16C5X family and not needing various peripheral features of other members of the PIC16XX mid-range microcontroller family.

1.2 Development Support

The PIC16C62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low-cost development programmer and a full-featured programmer. A "C" compiler and fuzzy logic support tools are also available.

TABLE 1-1: PIC16C62X FAMILY OF DEVICES

		PIC16C620	PIC16C620A	PIC16CR620A	PIC16C621	PIC16C621A	PIC16C622	PIC16C622A
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	512	512	1K	1K	2K	2K
	Data Memory (bytes)	80	96	96	80	96	128	128
	Timer Module(s)	TMR0	TMR0	TMRO	TMR0	TMR0	TMR0	TMR0
Peripherals	Comparators(s)	2	2	2	2	2	2	2
	Internal Reference Voltage	Yes						
	Interrupt Sources	4	4	4	4	4	4	4
	I/O Pins	13	13	13	13	13	13	13
_	Voltage Range (Volts)	2.5-6.0	3.0-5.5	2.5-5.5	2.5-6.0	3.0-5.5	2.5-6.0	3.0-5.5
Features	Brown-out Reset	Yes						
	Packages	18-pin DIP, SOIC; 20-pin SSOP						

All PICmicro™ Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C62X Family devices use serial programming with clock pin RB6 and data pin RB7.

2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

2.2 <u>One-Time-Programmable (OTP)</u> Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 <u>Serialized</u> <u>Quick-Turnaround-Production</u> (SQTPSM) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

PIC16C62X

NOTES:

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16C62X family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16C62X uses a Harvard architecture, in which, program and data are accessed from separate memories using separate busses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched from the same memory. Separating program and data memory further allows instructions to be sized differently than 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (35) execute in a single-cycle (200 ns @ 20 MHz) except for program branches.

The PIC16C620A and PIC16CR620A address 512 x 14 on-chip program memory. The PIC16C621(A) addresses 1K x 14 program memory. The PIC16C622(A) addresses 2K x 14 program memory. All program memory is internal.

The PIC16C62X can directly or indirectly address its register files or data memory. All special function registers including the program counter are mapped in the data memory. The PIC16C62X have an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16C62X simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC16C62X devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bit wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a $\overline{\text{Borrow}}$ and $\overline{\text{Digit}}$ $\overline{\text{Borrow}}$ out bit, respectively, bit in subtraction. See the SUBLW and SUBWF instructions for examples.

A simplified block diagram is shown in Figure 3-1, with a description of the device pins in Table 3-1.

FIGURE 3-1: BLOCK DIAGRAM

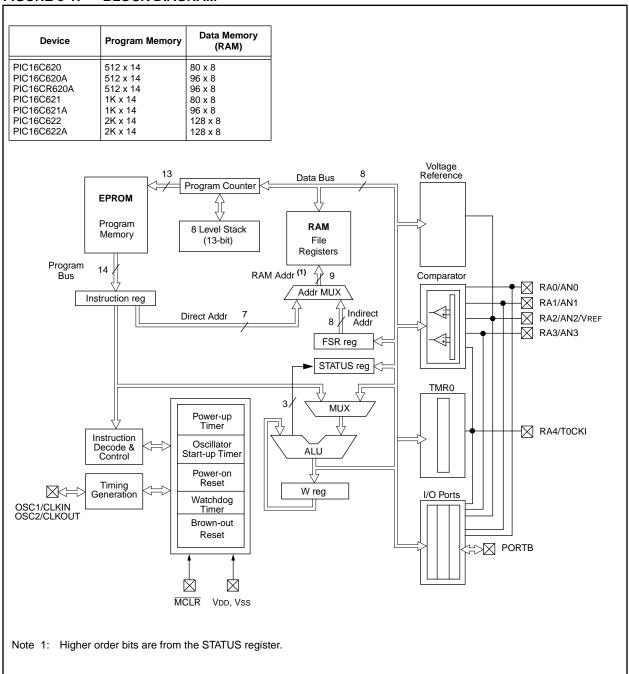


TABLE 3-1: PIC16C62X PINOUT DESCRIPTION

Name	DIP/ SOIC Pin #	SSOP Pin #	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	18	I	ST/CMOS	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	17	0	_	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master clear (reset) input/programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0/AN0	17	19	I/O	ST	Analog comparator input
RA1/AN1	18	20	I/O	ST	Analog comparator input
RA2/AN2/VREF	1	1	I/O	ST	Analog comparator input or VREF output
RA3/AN3	2	2	I/O	ST	Analog comparator input /output
RA4/T0CKI	3	3	I/O	ST	Can be selected to be the clock input to the Timer0 timer/counter or a comparator output. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	6	7	I/O	TTL/ST ⁽¹⁾	RB0/INT can also be selected as an external interrupt pin.
RB1	7	8	I/O	TTL	
RB2	8	9	I/O	TTL	
RB3	9	10	I/O	TTL	
RB4	10	11	I/O	TTL	Interrupt on change pin.
RB5	11	12	I/O	TTL	Interrupt on change pin.
RB6	12	13	I/O	TTL/ST ⁽²⁾	Interrupt on change pin. Serial programming clock.
RB7	13	14	I/O	TTL/ST ⁽²⁾	Interrupt on change pin. Serial programming data.
Vss	5	5,6	Р	_	Ground reference for logic and I/O pins.
VDD	14	15,16	Р	_	Positive supply for logic and I/O pins.

Legend:

O = output — = Not used

I/O = input/output

P = power

I = Input

ST = Schmitt Trigger input

TTL = TTL inputNote 1: This buffer is a Schmitt Trigger input when configured as the external interrupt. Note 2: This buffer is a Schmitt Trigger input when used in serial programming mode.

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3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

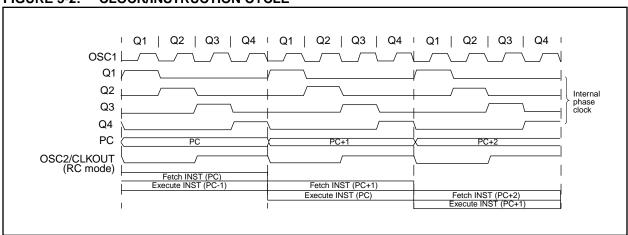
3.2 <u>Instruction Flow/Pipelining</u>

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

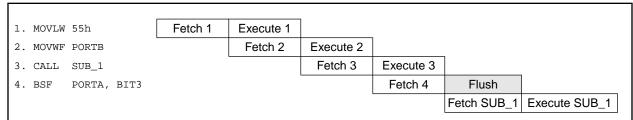
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).





EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

4.0 MEMORY ORGANIZATION

4.1 **Program Memory Organization**

The PIC16C62X has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C620(A) and PIC16CR620, 1K x 14 (0000h - 03FFh) for the PIC16C621(A) and 2K x 14 (0000h - 07FFh) for the PIC16C622(A) are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 space (PIC16C(R)620(A)) or 1K x 14 space (PIC16C621(A)) or 2K x 14 space (PIC16C622(A)). The reset vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2, Figure 4-3).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C620/PIC16C620A/ PIC16CR620A

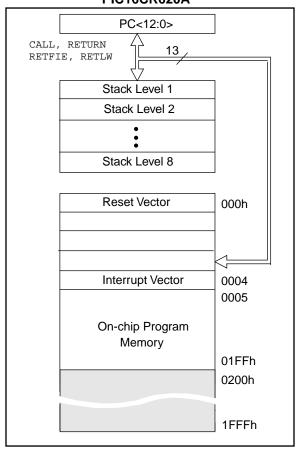


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C621/PIC16C621A

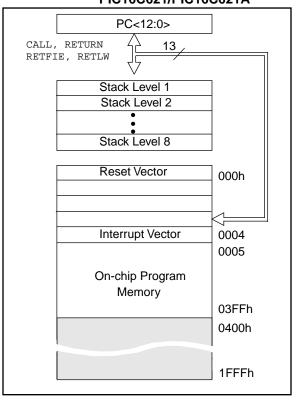
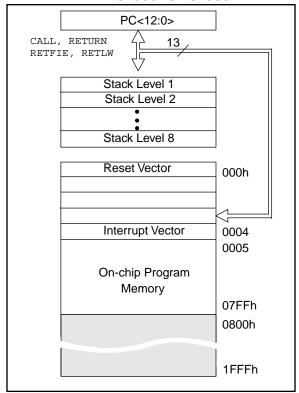


FIGURE 4-3: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C622/PIC16C622A



4.2 <u>Data Memory Organization</u>

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two Banks which contain the general purpose registers and the special function registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each Bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are general purpose registers implemented as static RAM. Some special purpose registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/CR620A/621A/622A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

FIGURE 4-4: DATA MEMORY MAP FOR THE PIC16C620/621

	THE PIC	160620/621	
File Address	i		File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h 6Fh 70h	General Purpose Register		A0h
			\supset
			FFh
7Fh [[]	Bank 0	Bank 1	— rrn ∣
	elemented data me Not a physical regi	emory locations, re	ead as '0'.

FIGURE 4-5: DATA MEMORY MAP FOR THE PIC16C622

	11111110	100022	
File Address	i		File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	. 0.0.2	111102	87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
07th	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh	1 11 1	1 151	8Dh
0Eh		PCON	8Eh
0Fh		rcon	8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			9311 94h
15h			95h
16h			96h
17h			97h
1711 18h			_ `
- H			98h 99h
19h			
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	014001	\/D00N	9Eh
1Fh	CMCON	VRCON	9Fh
20h	General	General	A0h
	Purpose	Purpose	
	Register	Register	BFh
			_
			C0h
			- -
7Fh		_	FFh
	Bank 0	Bank 1	
	lemented data me Not a physical regis		ead as '0'.

FIGURE 4-6: DATA MEMORY MAP FOR THE PIC16C620A/ CR620A/621A

	CR620A/62	21A	
File Address	S		File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h	General Purpose Register		A0h
6Fh			
70h			F0h
		Accesses 70h-7Fh	FFh
7Fh [[]	Bank 0	Bank 1	→ FFII
	olemented data me Not a physical regi		ead as '0'.

FIGURE 4-7: DATA MEMORY MAP FOR THE PIC16C622A

	1112110	IOOUZZA	1
File Address	3		File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
02h	STATUS	STATUS	83h
03h	FSR	FSR	- 84h
- 1			—
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			_ 88h
09h			89h
0Ah	PCLATH	PCLATH	_ 8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
- +			96h
16h			
17h			97h
18h			98h
19h			99h
1Ah			_ 9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h			A0h
	General Purpose	General Purpose	
	Register	Register	
			BFh
			C0h
6Fh			
70h			F0h
7 011		Accesses 70h-7Fh	
7Fh			\rfloor FFh
7111	Bank 0	Bank 1	
Unimp	olemented data me	mory locations, re	ead as '0'.
	Not a physical regis		

4.2.2 SPECIAL FUNCTION REGISTERS

The special function registers are registers used by the CPU and Peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM.

The special registers can be classified into two sets (core and peripheral). The special function registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16C62X

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other resets ⁽¹⁾
Bank 0											
00h	INDF	Addressin register)	g this locat	ion uses co	ntents of F	SR to addre	ess data me	emory (not a	a physical	xxxx xxxx	xxxx xxxx
01h	TMR0	Timer0 M	odule's Reg	jister						xxxx xxxx	uuuu uuuu
02h	PCL	Program (Counter's (F	PC) Least S	ignificant B	yte				0000 0000	0000 0000
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h	FSR	Indirect da	ata memory	address p	ointer				I	xxxx xxxx	uuuu uuuu
05h	PORTA	_	_	_	RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	Unimplemented									_	-
08h	Unimplemented									_	-
09h	Unimplemented									_	_
0Ah	PCLATH	_	_	_	Write buffe	er for upper	5 bits of pr	ogram cou	nter	0 0000	0 0000
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	_	CMIF	_	_	_	_	_	_	-0	-0
0Dh-1Eh	Unimplemented									_	-
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
Bank 1									•		
80h	INDF	Addressin register)	g this locat	ion uses co	ntents of F	SR to addre	ess data me	emory (not a	a physical	xxxx xxxx	xxxx xxxx
81h	OPTION	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program (Counter's (F	PC) Least S	ignificant B	yte				0000 0000	0000 0000
83h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h	FSR	Indirect da	ata memory	address p	ointer					xxxx xxxx	uuuu uuuu
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h	Unimplemented									_	-
88h	Unimplemented									_	-
89h	Unimplemented									_	-
8Ah	PCLATH	_	_	_	Write buffe	er for upper	5 bits of pr	ogram cou	nter	0 0000	0 0000
8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	_	CMIE	_	_	_	_	_	_	-0	-0
8Dh	Unimplemented									-	-
8Eh	PCON	_	_	_	_	_	_	POR	BOR	0x	uq
8Fh-9Eh	Unimplemented									-	-
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non power-up) resets include MCLR reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

Note 2: IRP & RPI bits are reserved, always maintain these bits clear.

4.2.2.1 STATUS REGISTER

The STATUS register, shown in Figure 4-8, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the status register as 000uuluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect any status bit. For other instructions, not affecting any status bits, see the "Instruction Set Summary".

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16C62X and should be programmed as '0'. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

Note 2: The C and DC bits operate as a Borrow and Digit Borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

FIGURE 4-8: STATUS REGISTER (ADDRESS 03H OR 83H)

Reserved	d Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x	
IRP	RP1	RP0	TO	PD	Z	DC	С	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset -x = Unknown at POR reset
bit 7:	IRP: Regis 1 = Bank 2 0 = Bank 0	2, 3 (100h	- 1FFh)	used for ir	ndirect addr	essing)		

bit 6-5: RP1:RP0: Register Bank Select bits (used for direct addressing)

The IRP bit is reserved on the PIC16C62X, always maintain this bit clear.

- 11 = Bank 3 (180h 1FFh)
- 10 = Bank 2 (100h 17Fh)
- 01 = Bank 1 (80h FFh)
- 00 = Bank 0 (00h 7Fh)

Each bank is 128 bytes. The RP1 bit is reserved on the PIC16C62X, always maintain this bit clear.

- bit 4: **TO**: Time-out bit
 - 1 = After power-up, CLRWDT instruction, or SLEEP instruction
 - 0 = A WDT time-out occurred
- bit 3: **PD**: Power-down bit
 - 1 = After power-up or by the CLRWDT instruction
 - 0 = By execution of the ${\tt SLEEP}$ instruction
- bit 2: Z: Zero bit
 - 1 = The result of an arithmetic or logic operation is zero
 - 0 = The result of an arithmetic or logic operation is not zero
- bit 1: DC: Digit carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)(for borrow the polarity is reversed)
 - 1 = A carry-out from the 4th low order bit of the result occurred
 - 0 = No carry-out from the 4th low order bit of the result
- bit 0: C: Carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)
 - 1 = A carry-out from the most significant bit of the result occurred
 - 0 = No carry-out from the most significant bit of the result occurred

Note: For borrow the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low order bit of the source register.

4.2.2.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

FIGURE 4-9: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	R = Readable bit
bit7							bit0	W = Writable bit - n = Value at POR reset
bit 7:	RBPU : PO 1 = PORTE 0 = PORTE	3 pull-ups	are disal	oled	lividual port	latch valu	es	
bit 6:	INTEDG: In 1 = Interru 0 = Interru	ot on risin	g edge o	f RB0/INT				
bit 5:	TOCS : TMF 1 = Transiti 0 = Interna	on on RA	4/T0CKI	pin	(OUT)			
bit 4:		ent on hig	h-to-low	transition	on RA4/T00 on RA4/T00			
bit 3:	PSA: Presca 1 = Presca 0 = Presca	ler is assi	gned to t	he WDT	module			
bit 2-0:	PS2:PS0:	Prescaler	Rate Sel	ect bits				
	Bit Value	TMR0 Ra	ate WD	ΓRate				
	000 001 010 011 100 101 110	1:2 1:4 1:8 1:16 1:32 1:64 1:128	1:	2				

4.2.2.3 INTCON REGISTER

The INTCON register is a readable and writable register which contains the various enable and flag bits for all interrupt sources except the comparator module. See Section 4.2.2.4 and Section 4.2.2.5 for a description of the comparator enable and flag bits.

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

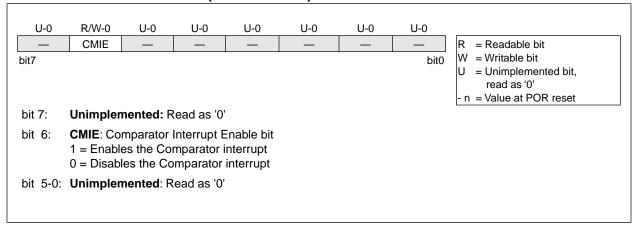
FIGURE 4-10: INTCON REGISTER (ADDRESS 0BH OR 8BH)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x			
GIE it7	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF bit0	R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset		
oit 7:		oal Interrup es all un-r les all inte	masked in					-x = Unknown at POR reset		
bit 6:	PEIE : Per 1 = Enabl 0 = Disab	es all un-r	nasked pe	eripheral ir	nterrupts					
bit 5:	TOIE: TMR0 Overflow Interrupt Enable bit 1 = Enables the TMR0 interrupt 0 = Disables the TMR0 interrupt									
bit 4:	INTE: RB0/INT External Interrupt Enable bit 1 = Enables the RB0/INT external interrupt 0 = Disables the RB0/INT external interrupt									
bit 3:	RBIE: RB 1 = Enabl 0 = Disab	es the RB	port char	ige interru	pt					
bit 2:	1 = TMR0	R0 Overflo register h	nas overflo	wed (mus	t be cleared	d in softwa	re)			
bit 1:			cternal inte	errupt occi	urred (must	be cleared	d in softwar	re)		
bit 0:		at least o	ne of the	RB7:RB4			nust be clea	ared in software)		

4.2.2.4 PIE1 REGISTER

This register contains the individual enable bit for the comparator interrupt.

FIGURE 4-11: PIE1 REGISTER (ADDRESS 8CH)

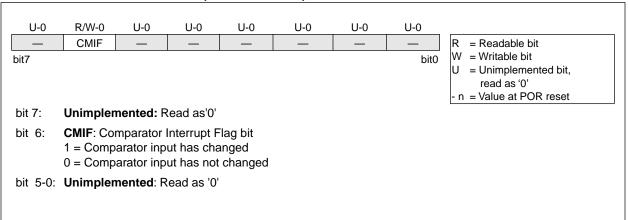


4.2.2.5 PIR1 REGISTER

This register contains the individual flag bit for the comparator interrupt.

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-12: PIR1 REGISTER (ADDRESS 0CH)



4.2.2.6 PCON REGISTER

The PCON register contains flag bits to differentiate between a Power-on Reset, an external MCLR reset, WDT reset or a Brown-out Reset.

Note: BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if BOR is cleared, indicating a brown-out has occurred. The BOR status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BOREN bit in the Configuration word).

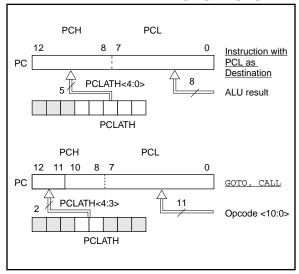
FIGURE 4-13: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0			
_	_	_	_	_	_	POR	BOR	R = Readable bit		
bit7 bit 7-2:	Unimpler	mented: F	Read as '0				bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset		
bit 1:	Unimplemented: Read as '0' POR: Power-on Reset Status bit 1 = No Power-on Reset occurred 0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)									
bit 0:	BOR : Bro 1 = No Bro 0 = A Bro	own-out F	Reset occu	ırred	be set in sc	oftware afte	er a Brown	-out Reset occurs)		

4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any reset, the PC is cleared. Figure 4-14 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> \rightarrow PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> \rightarrow PCH).

FIGURE 4-14: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note "Implementing a Table Read" (AN556).

4.3.2 STACK

The PIC16C62X family has an 8 level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

- Note 1: There are no STATUS bits to indicate stack overflow or stack underflow conditions.
- Note 2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

4.4 <u>Indirect Addressing, INDF and FSR</u> Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the file select register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-15. However, IRP is not used in the PIC16C62X.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

movlw 0x20 ;initialize pointer

movwf FSR ;to RAM

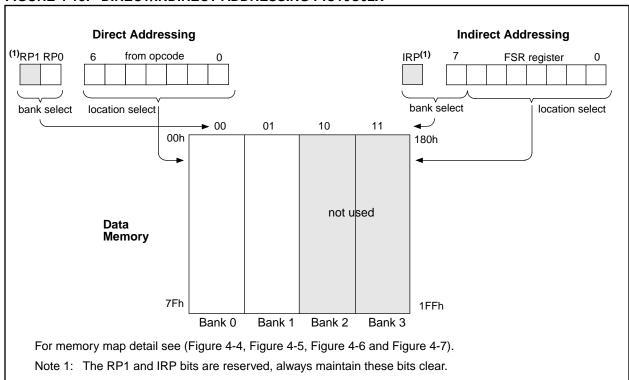
NEXT clrf INDF ; clear INDF register

incf FSR ;inc pointer
btfss FSR,4 ;all done?
goto NEXT ;no clear next

;yes continue

CONTINUE:

FIGURE 4-15: DIRECT/INDIRECT ADDRESSING PIC16C62X



5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

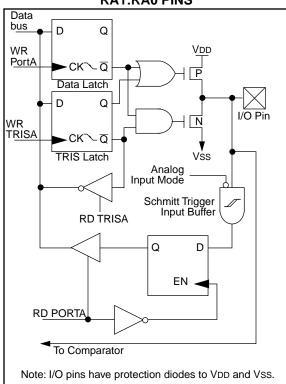
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the TOCKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a hi- impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS



Note: On reset, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

CLRF PORTA ; Initialize PORTA by setting ;output data latches MOVLW 0X07 ;Turn comparators off and MOVWF CMCON ;enable pins for I/O ;functions BSF STATUS, RPO ; Select Bank1 ; Value used to initialize MOVIW 0x1F ;data direction MOVWF TRISA ;Set RA<4:0> as inputs ;TRISA<7:5> are always ;read as '0'.

FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN

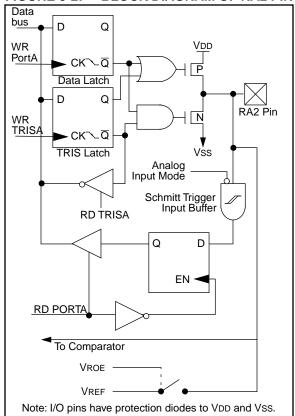


FIGURE 5-3: BLOCK DIAGRAM OF RA3 PIN

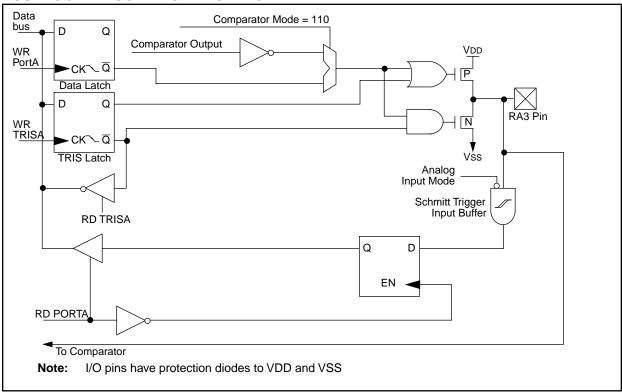


FIGURE 5-4: BLOCK DIAGRAM OF RA4 PIN

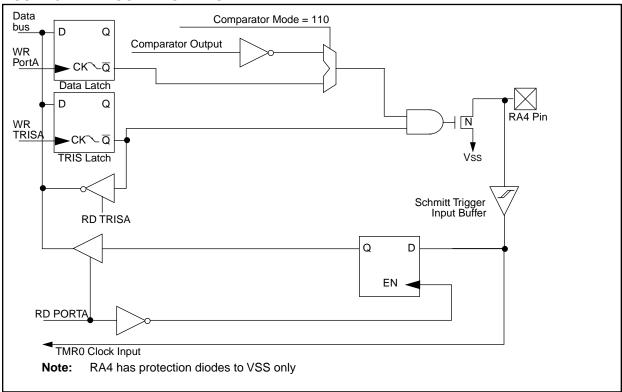


TABLE 5-1: PORTA FUNCTIONS

Name	Bit #	Buffer Type	Function				
RA0/AN0	bit0	ST	Input/output or comparator input				
RA1/AN1	bit1	ST	Input/output or comparator input				
RA2/AN2/VREF	bit2	ST	Input/output or comparator input or VREF output				
RA3/AN3	bit3	ST	Input/output or comparator input/output				
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0 or comparator output. Output is open drain type.				

Legend: ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
05h	PORTA	_	_	_	RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Note: Shaded bits are not used by PORTA.

5.2 PORTB and TRISB Registers

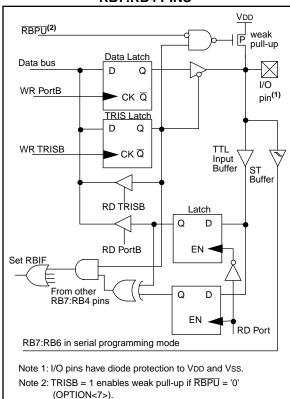
PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up ($\approx 200~\mu A$ typical). A single control bit can turn on all the pull-ups. This is done by clearing the \overline{RBPU} (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB7:RB4 PINS



This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of PORTB. This will end the mismatch condition.
- b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552 in the Microchip *Embedded Control Handbook.*)

Note: If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB3:RB0 PINS

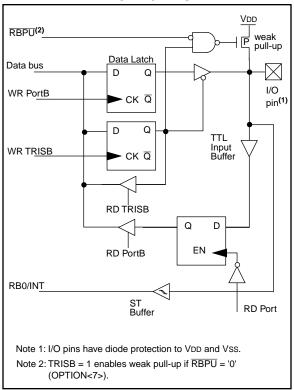


TABLE 5-3: PORTB FUNCTIONS

Name	Bit #	Buffer Type	Function
RB0/INT	bit0	TTL/ST ⁽¹⁾	Input/output or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock pin.
RB7	bit7	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data pin.

Legend: ST = Schmitt Trigger, TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt. Note 2: This buffer is a Schmitt Trigger input when used in serial programming mode.

TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Note: Shaded bits are not used by PORTB.

u = unchanged x = unknown

5.3 **I/O Programming Considerations**

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (ex., BCF, BSF, etc.) on an I/O port

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

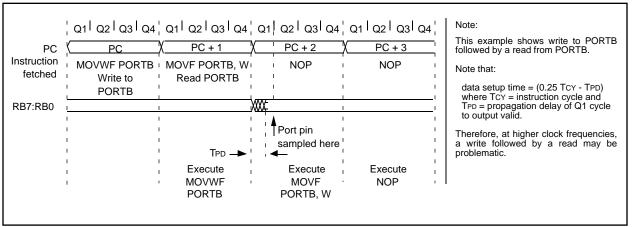
EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
; Initial PORT settings: PORTB<7:4> Inputs
                          PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
                          PORT latch PORT pins
    BCF PORTB. 7
                         ; 01pp pppp
                                     11pp pppp
    BCF PORTB, 6
                         ; 10pp pppp
                                      11pp pppp
    BSF STATUS, RP0
    BCF TRISB, 7
                         ; 10pp pppp
                                      11pp pppp
    BCF TRISB. 6
                         ; 10pp pppp
                                      10pp pppp
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.





6.0 TIMERO MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- · Readable and writable
- · 8-bit software programmable prescaler
- · Internal or external clock select
- · Interrupt on overflow from FFh to 00h
- · Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the TOCS bit (OPTION<5>). In timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to TMR0.

Counter mode is selected by setting the ToCS bit. In this mode Timer0 will increment either on every rising or falling edge of pin RA4/ToCKI. The incrementing edge is determined by the source edge (ToSE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

6.1 TIMER0 Interrupt

Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMERO BLOCK DIAGRAM

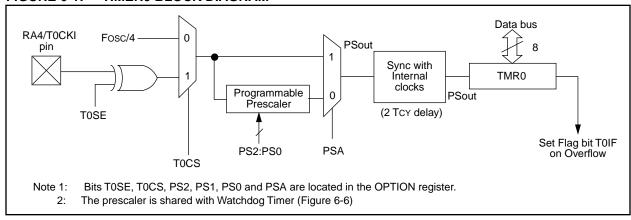


FIGURE 6-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER

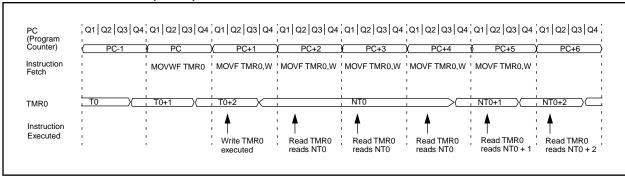


FIGURE 6-3: TIMERO TIMING: INTERNAL CLOCK/PRESCALE 1:2

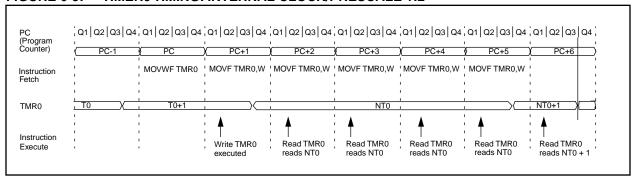
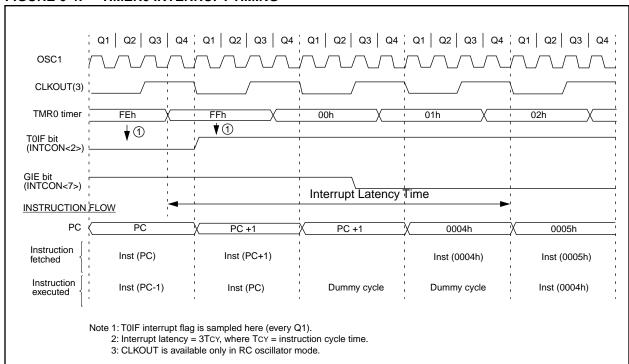


FIGURE 6-4: TIMERO INTERRUPT TIMING



6.2 <u>Using Timer0 with External Clock</u>

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

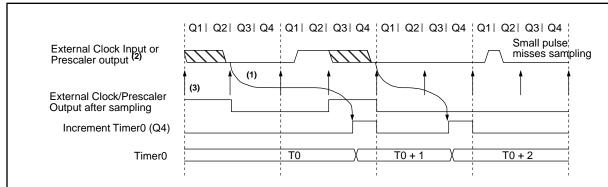
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for TOCKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on TOCKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

6.2.2 TIMERO INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMERO TIMING WITH EXTERNAL CLOCK



- Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4 Tosc max.
 - 2: External clock if no prescaler selected, Prescaler output otherwise.
 - 3: The arrows indicate the points in time where sampling occurs.

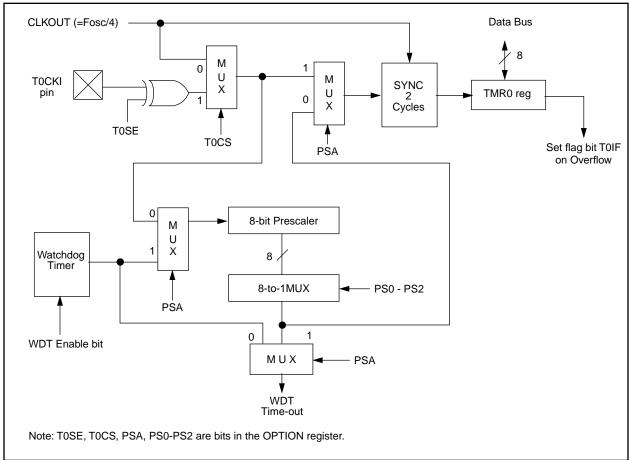
6.3 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that there is only one prescaler available which is mutually exclusive between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1,x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

FIGURE 6-6: BLOCK DIAGRAM OF THE TIMERO/WDT PRESCALER



6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on the fly" during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

1.BCF STATUS, RPO ; Skip if already in ; Bank 0 ;Clear WDT 2.CLRWDT TMR0 ;Clear TMR0 & Prescaler STATUS, RP0 ;Bank 1 3.CLRF TMR0 4.BSF 5.MOVLW '00101111'b; ;These 3 lines (5, 6, 7) 6.MOVWF OPTION ; are required only if ; desired PS<2:0> are 7.CLRWDT ; 000 or 001 8.MOVLW '00101xxx'b ;Set Postscaler to 9.MOVWF OPTION ; desired WDT rate 10.BCF STATUS, RPO ; Return to Bank 0

To change prescaler from the WDT to the TMR0 module use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

CLRWDT ;Clear WDT and ;prescaler

BSF STATUS, RP0

MOVLW

b'xxxx0xxx' ;Select TMR0, new

;prescale value and

;clock source

MOVWF OPTION_REG BCF STATUS, RP0

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMERO

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
01h	TMR0	Timer0	module regi	xxxx xxxx	uuuu uuuu						
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: — = Unimplemented locations, read as '0'.

Note: Shaded bits are not used by TMR0 module.

u = unchanged
x = unknown

PIC16C62X

NOTES:

7.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RAO through RA3 pins. The on-chip Voltage Reference (Section 8.0) can also be an input to the comparators.

The CMCON register, shown in Figure 7-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 7-2.

FIGURE 7-1: CMCON REGISTER (ADDRESS 1Fh)

R-0	R-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	
C2OUT	C10UT			CIS	CM2	CM1	CM0	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:	C2OUT : Cor 1 = C2 VIN+ 0 = C2 VIN+	> C2 V	IN-	out				
bit 6:	C1OUT: Con 1 = C1 VIN+ 0 = C1 VIN+	> C1 V	IN-	out				
bit 5-4:	Unimpleme	nted: R	lead as	'0'				
bit 3:	CIS: Compa When CM<2 1 = C1 VIN- 0 = C1 VIN- When CM<2 1 = C1 VIN- C2 VIN- C2 VIN- C2 VIN-	2:0>: = (connection of the connection of the co	DO1: tts to RA tts to RA 10: tts to RA cts to RA cts to RA	A3 A0 A3 A2 A0				
bit 2-0:	CM<2:0> : C Figure 7-2.	ompara	itor mod	е				

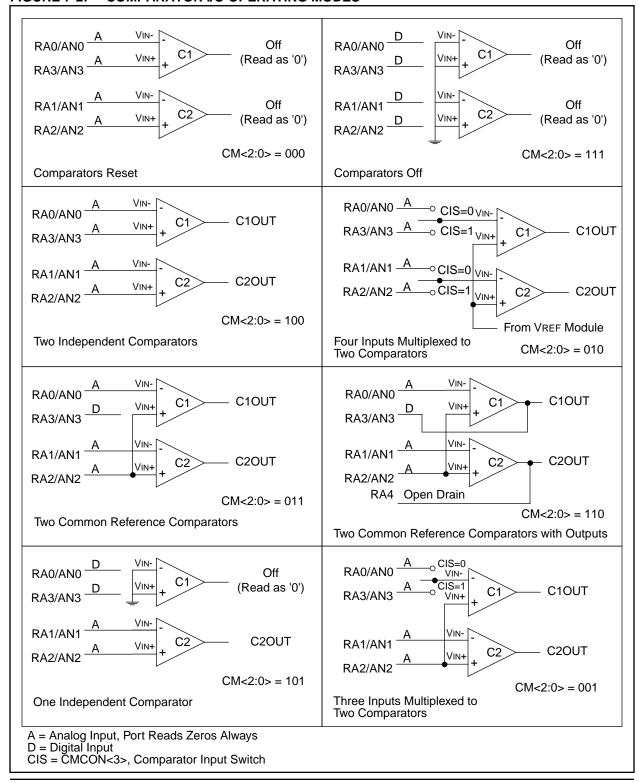
7.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 7-2 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the comparator mode is

changed, the comparator output level may not be valid for the specified mode change delay shown in Table 12-2.

Note: Comparator interrupts should be disabled during a comparator mode change otherwise a false interrupt may occur.

FIGURE 7-2: COMPARATOR I/O OPERATING MODES



The code example in Example 7-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

EXAMPLE 7-1: INITIALIZING COMPARATOR MODULE

FLAG_REG	EQU	0X20
CLRF	FLAG_REG	;Init flag register
CLRF	PORTA	;Init PORTA
MOVF	CMCON, W	;Load comparator bits
ANDLW	0xC0	:Mask comparator bits
IORWF	FLAG_REG,F	Store bits in flag register
MOVLW	0x03	;Init comparator mode
MOVWF	CMCON	;CM<2:0> = 011
BSF	STATUS, RP0	;Select Bankl
MOVLW	0x07	;Initialize data direction
MOVWF	TRISA	;Set RA<2:0> as inputs
		;RA<4:3> as outputs
		;TRISA<7:5> always read '0'
BCF	STATUS, RP0	;Select Bank 0
CALL	DELAY 10	;10µs delay
MOVF	CMCON, F	Read CMCON to end change condition
BCF	PIR1,CMIF	Clear pending interrupts
BSF	STATUS, RP0	;Select Bank 1
BSF	PIE1,CMIE	;Enable comparator interrupts
BCF	STATUS, RP0	;Select Bank 0
BSF	INTCON, PEIE	Enable peripheral interrupts
BSF	INTCON, GIE	;Global interrupt enable

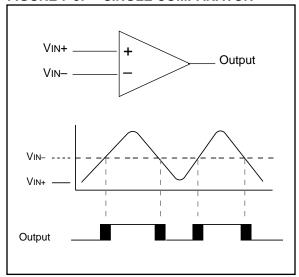
7.2 <u>Comparator Operation</u>

A single comparator is shown in Figure 7-3 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 7-3 represent the uncertainty due to input offsets and response time.

7.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator operating mode. The analog signal that is present at VIN— is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 7-3).

FIGURE 7-3: SINGLE COMPARATOR



7.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD, and can be applied to either pin of the comparator(s).

7.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 13, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 7-2). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

7.4 <u>Comparator Response Time</u>

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output is guaranteed to have a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise the maximum delay of the comparators should be used (Table 12-2).

7.5 Comparator Outputs

The comparator outputs are read through the CMCON register. These bits are read only. The comparator outputs may also be directly output to the RA3 and RA4 I/O pins. When the CM<2:0> = 110, multiplexors in the output path of the RA3 and RA4 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 7-4 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/disable for the RA3 and RA4 pins while in this mode.

- Note 1: When reading the PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the Schmitt Trigger input specification.
 - 2: Analog levels on any pin that is defined as a digital input may cause the input buffer to consume more current than is specified.

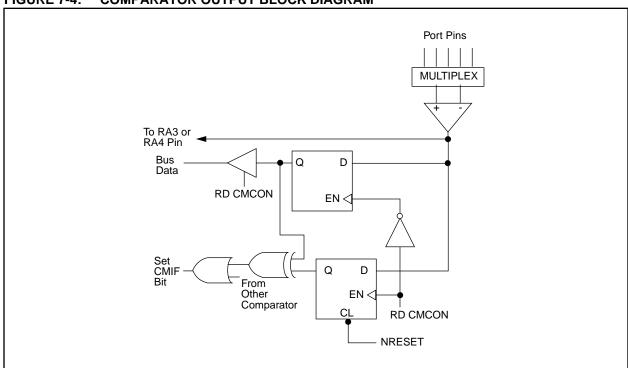


FIGURE 7-4: COMPARATOR OUTPUT BLOCK DIAGRAM

7.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note: If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

- Any read or write of CMCON. This will end the mismatch condition.
- b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

7.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

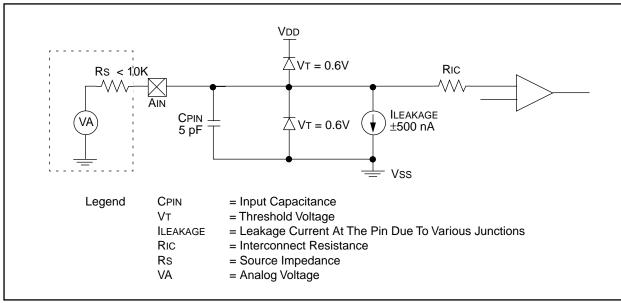
7.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM2:CM0 = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

7.9 <u>Analog Input Connection</u> Considerations

A simplified circuit for an analog input is shown in Figure 7-5. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and Vss. The analog input therefore, must be between Vss and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 k $\!\Omega$ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 7-5: ANALOG INPUT MODEL



PIC16C62X

TABLE 7-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	_	CMIF	_	_	_	_	_	_	-0	-0
8Ch	PIE1	_	CMIE	_	_	_	_	_	_	-0	-0
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: x = unknown

u = unchanged

- = unimplemented, read as "0"

8.0 VOLTAGE REFERENCE MODULE

The Voltage Reference is a 16-tap resistor ladder network that provides a selectable voltage reference. The resistor ladder is segmented to provide two ranges of VREF values and has a power-down function to conserve power when the reference is not being used. The VRCON register controls the operation of the reference as shown in Figure 8-1. The block diagram is given in Figure 8-2.

8.1 Configuring the Voltage Reference

The Voltage Reference can output 16 distinct voltage levels for each range.

The equations used to calculate the output of the Voltage Reference are as follows:

if VRR = 1: $VREF = (VR < 3:0 > /24) \times VDD$

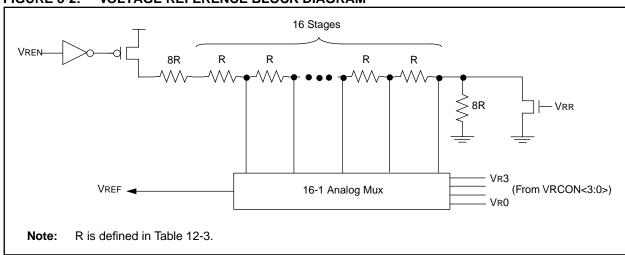
if VRR = 0: VREF = (VDD x 1/4) + (VR < 3:0 > /32) x VDD

The setting time of the Voltage Reference must be considered when changing the VREF output (Table 12-2). Example 8-1 shows an example of how to configure the Voltage Reference for an output voltage of 1.25V with VDD = 5.0V.

FIGURE 8-1: VRCON REGISTER(ADDRESS 9Fh)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	
VREN	VROE	Vrr	_	VR3	VR2	VR1	VR0	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:		Enable EF circuit p EF circuit p			IDD drain			
bit 6:		Output Ender is outputed in the Ender is outputed in the Ender in the	it on RA	•	2 pin			
bit 5:		Range selo w Range gh Range	ection					
bit 4:	Unimplem	ented: Rea	ad as '0					
bit 3-0:		√RR = 1: VF	REF = (V	/R<3:0>/ 2	-	32) * Vdd		

FIGURE 8-2: VOLTAGE REFERENCE BLOCK DIAGRAM



EXAMPLE 8-1: VOLTAGE REFERENCE CONFIGURATION

MOVLW	0x02	;	4 Inputs Muxed
MOVWF	CMCON	;	to 2 comps.
BSF	STATUS, RPO	;	go to Bank 1
MOVLW	0x07	;	RA3-RA0 are
MOVWF	TRISA	;	outputs
MOVLW	0xA6	;	enable VREF
MOVWF	VRCON	;	low range
		;	set VR<3:0>=6
BCF	STATUS, RPO	;	go to Bank 0
CALL	DELAY10	;	10μs delay

8.2 <u>Voltage Reference Accuracy/Error</u>

The full range of Vss to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 8-2) keep VREF from approaching Vss or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The tested absolute accuracy of the Voltage Reference can be found in Table 12-3.

8.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

8.4 Effects of a Reset

A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

8.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 8-3 shows an example buffering technique.

FIGURE 8-3: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE

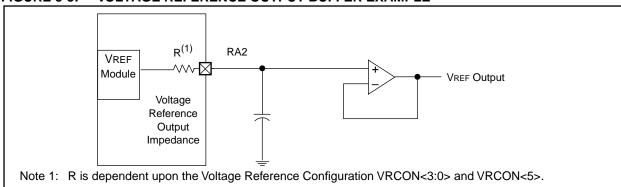


TABLE 8-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
85h	TRISA	_	_		TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Note: -= Unimplemented, read as "0"

9.0 SPECIAL FEATURES OF THE CPU

Special circuits to deal with the needs of real time applications are what sets a microcontroller apart from other processors. The PIC16C62X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

- 1. OSC selection
- 2. Reset

Power-on Reset (POR) Power-up Timer (PWRT) Oscillator Start-Up Timer (OST) Brown-out Reset (BOR)

- 3. Interrupts
- 4. Watchdog Timer (WDT)
- 5. SLEEP
- 6. Code protection
- 7. ID Locations
- 8. In-circuit serial programming

The PIC16C62X has a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs which provides at least a 72 ms reset. With these three functions on-chip, most applications need no external reset circuitry.

The SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external reset, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

9.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h-3FFfh), which can be accessed only during programming.

FIGURE 9-1: CONFIGURATION WORD

CP1	CPO	(2)	CP1	CP0(2)	CP1	CP0 ⁽²⁾	— B	OREN(1)	CP1	CP0 ⁽²⁾	PWRTE(1)	WDTE	F0SC1	F0SC0	CONFIG	Address
bit13				1									I.	bit0	REGISTER	: 2007h
bit 13-		Cod 11 = 10 = 01 = 000 = Cod 11 = 00 = Cod 11 = 00 = 00 = 00 = 00 =	le pro = Prog = 0400 = 0200 = 0000 de prog = Prog = 0200 = 0000 de prog = Prog = Prog = Prog = Prog	prection gram me ph-07FF ph-07FF ptection gram me ph-03FF ph-03FF ptection gram me gram me gram me gram me	for 2K emory of th code th code for 1K emory of th code th code for 0.5 emory of emory of emory of	bit pairs programment protects	m mei tection ed ed ed m mei tection ed ed ram m tectior tectior	mory off on emory off off						bite		. 2001
bit 7:				mented			-u									
bit 6:		BOI 1 =	REN: BOR		out Res	et Enabl	le bit ⁽¹	1)								
bit 3:		1 =	PWR ⁻	Power-u Γ disabl Γ enable	ed	r Enable	e bit ^{(1,}	3)								
bit 2:		1 = 1	WDT	atchdoo enabled disabled	ĺ	Enable	bit									
bit 1-6	0:	11 = 10 = 01 =	= RC (= HS (= XT (OSCO: oscillato oscillato oscillato oscillato	r r r	or Selec	ction bi	its								
ı	2:	reco	omme of the	nd that CP1:CF	whene 0 pairs	er Brow have to	n-out l be giv	Reset is	enable ame va	d, the Palue to e	mer (PWR ower-up T enable the	imer is	also ena	abled.	e of bit PWR	TE. We

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16C62X can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

LP Low Power CrystalXT Crystal/Resonator

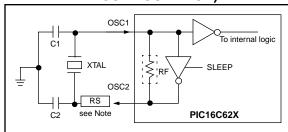
• HS High Speed Crystal/Resonator

• RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 9-2). The PIC16C62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 9-3).

FIGURE 9-2: CRYSTAL OPERATION
(OR CERAMIC RESONATOR)
(HS, XT OR LP OSC
CONFIGURATION)



See Table 9-1 and Table 9-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

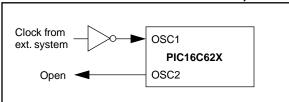


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges	Characterized:	1	
Mode	Freq	OSC1(C1)	OSC2(C2)
XT	455 kHz	22 - 100 pF	22 160 pF
	2.0 MHz	15 - 68 pF	15 68 pF
	4.0 MHz	15 - 68 pF	15 - 68 pF
HS	8.0 MHz	10-68 pF	10 - 68 pF
	16.0 MHz	10-22-pF	10 - 22 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manuary for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz	68 - 100 pF	68 - 100 pF
	200 kHz	15 - 30 pF	15 - 30 pF
ХТ	100 kHz	68 - 150 pF	150 - 200 pF
	2 MHz	15 - 30 pF	15 - 30 pF
	4 MHz	15 - 30 pF	15 - 30 pF
HS	8 MHz	15 - 30 pF	15 - 30 pF
	10 MHz	15 - 30 pF	15 - 30 pF
	20 MHz	15 - 30 pF	15 - 30 pF

Higher capacitance increases the stability of the oscillator but also increases the stability time. These values are for design guidance only. As may be required in HS mode as well as XT node to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

9.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance, or one with parallel resonance.

Figure 9-4 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 9-4: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

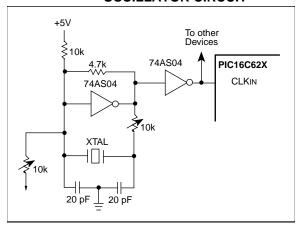
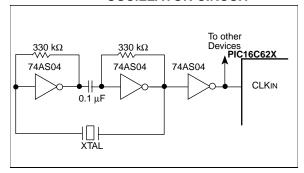


Figure 9-5 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 9-5: EXTERNAL SERIES
RESONANT CRYSTAL
OSCILLATOR CIRCUIT



9.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency. especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 9-6 shows how the R/C combination is connected to the PIC16C62X. For Rext values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g., 1 M Ω), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 k Ω and 100 k Ω .

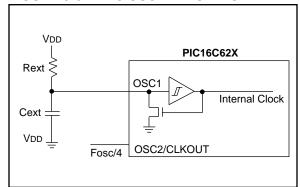
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 13.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 13.0 for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 9-6: RC OSCILLATOR MODE



9.3 Reset

The PIC16C62X differentiates between various kinds of reset:

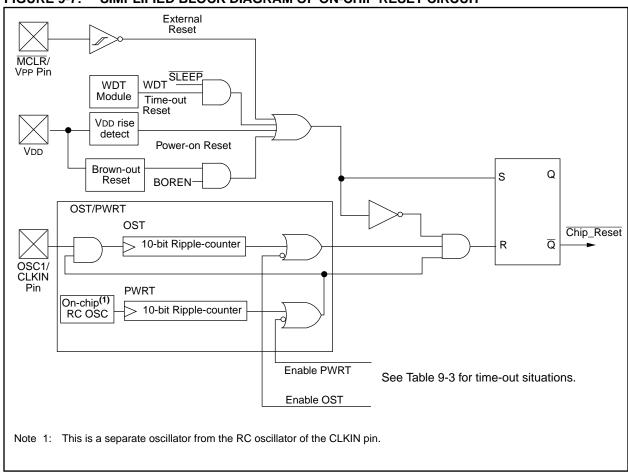
- a) Power-on reset (POR)
- b) MCLR reset during normal operation
- c) MCLR reset during SLEEP
- d) WDT reset (normal operation)
- e) WDT wake-up (SLEEP)
- f) Brown-out Reset (BOR)

Some registers are not affected in any reset condition; their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on reset, MCLR reset, WDT reset and MCLR reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. TO and PD bits are set or cleared differently in different reset situations as indicated in Table 9-4. These bits are used in software to determine the nature of the reset. See Table 9-7 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 9-7.

The MCLR reset path has a noise filter to detect and ignore small pulses. See Table 12-6 for pulse width specification.

FIGURE 9-7: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



9.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

The POR circuit does not produce an internal reset when VDD declines.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607 "Power-up Trouble Shooting".

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, PWRTE can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-Up Time delay will vary from chip to chip and due to VDD, temperature and process variation. See DC parameters for details.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on power-on reset or wake-up from SLEEP.

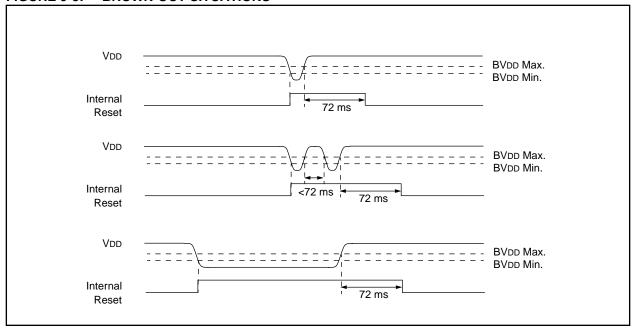
9.4.4 BROWN-OUT RESET (BOR)

The PIC16C62X members have on-chip Brown-out Reset circuitry. A configuration bit, BOREN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V refer to V_{BOR} parameter D005(V_{BOR}) for greater than parameter (TBOR) in Table 12-6, the brown-out situation will reset the chip. A reset is not guaranteed to occur if VDD falls below 4.0V for less than parameter (TBOR).

On any reset (Power-on, Brown-out, Watchdog, etc.) the chip will remain in Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in reset an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-8 shows typical Brown-out situations.





9.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and PWRTE bit status. For example, in RC mode with PWRTE bit erased (PWRT disabled), there will be no time-out at all. Figure 9-9, Figure 9-10 and Figure 9-11 depict time-out sequences.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (see Figure 9-10). This is useful for testing purposes or to synchronize more than one PIC16C62X device operating in parallel.

Table 9-6 shows the reset conditions for some special registers, while Table 9-7 shows the reset conditions for all the registers.

9.4.6 POWER CONTROL (PCON)/ STATUS REGISTER

The power control/status register, PCON (address 8Eh) has two bits.

Bit0 is \overline{BOR} (Brown-out). \overline{BOR} is unknown on power-on-reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}=0$ indicating that a brown-out has occurred. The \overline{BOR} status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BOREN bit = 0 in the Configuration word).

Bit1 is POR (Power-on-reset). It is a '0' on power-on-reset and unaffected otherwise. The user must write a '1' to this bit following a power-on-reset. On a subsequent reset if POR is '0', it will indicate that a power-on-reset must have occurred (VDD may have gone too low).

TABLE 9-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Powe	er-up	Brown-out Reset	Wake-up	
Oscillator Configuration	PWRTE = 0	PWRTE = 1	Brown-out Neset	from SLEEP	
XT, HS, LP	72 ms + 1024 Tosc	1024 Tosc	72 ms + 1024 Tosc	1024 Tosc	
RC	72 ms	_	72 ms	_	

TABLE 9-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOR	TO	PD	
0	Х	1	1	Power-on-reset
0	Х	0	Х	Illegal, TO is set on POR
0	Х	Х	0	Illegal, PD is set on POR
1	0	Х	Х	Brown-out Reset
1	1	0	u	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR reset during normal operation
1	1	1	0	MCLR reset during SLEEP

Legend: u = unchanged, x = unknown

TABLE 9-5: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other resets ⁽¹⁾		
83h	STATUS				TO	PD				0001 1xxx	000q quuu		
8Eh	8Eh PCON — — — — — — POR BOR0xuq												
Note1: Of	Note1: Other (non power-up) resets include MCLR reset, Brown-out Reset and Watchdog Timer Reset during normal operation.												

TABLE 9-6: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	0x
MCLR reset during normal operation	000h	000u uuuu	uu
MCLR reset during SLEEP	000h	0001 0uuu	uu
WDT reset	000h	0000 uuuu	uu
WDT Wake-up	PC + 1	uuu0 0uuu	uu
Brown-out Reset	000h	000x xuuu	u0
Interrupt Wake-up from SLEEP	PC + 1 ⁽¹⁾	uuu1 0uuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

TABLE 9-7: INITIALIZATION CONDITION FOR REGISTERS

Register	Address	Power-on Reset	MCLR Reset during normal operation MCLR Reset during SLEEP WDT Reset Brown-out Reset (1)	Wake up from SLEEP through interrupt Wake up from SLEEP through WDT time-out
W	-	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h	-	-	-
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000 0000	0000 0000	PC + 1 ⁽³⁾
STATUS	03h	0001 1xxx	000q quuu ⁽⁴⁾	uuuq quuu ⁽⁴⁾
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	05h	x xxxx	u uuuu	u uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
CMCON	1Fh	00 0000	00 0000	uu uuuu
PCLATH	0Ah	0 0000	0 0000	u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uqqq ⁽²⁾
PIR1	0Ch	-0	-0	-q(2,5)
OPTION	81h	1111 1111	1111 1111	uuuu uuuu
TRISA	85h	1 1111	1 1111	u uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
PIE1	8Ch	-0	-0	-u
PCON	8Eh	0x	uq ^(1,6)	uu
VRCON	9Fh	000- 0000	000- 0000	uuu- uuuu

 $\mbox{Legend: } u = \mbox{unchanged, } x = \mbox{unknown, } - = \mbox{unimplemented bit, reads as '0', } q = \mbox{value depends on condition.}$

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

- 2: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).
- 3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).
- 4: See Table 9-6 for reset value for specific condition.
- 5: If wake-up was due to comparator input changing, then bit 6 = 1. All other interrupts generating a wake-up will cause bit 6 = u.
- 6: If reset was due to brown-out, then bit 0 = 0. All other resets will cause bit 0 = u.

FIGURE 9-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

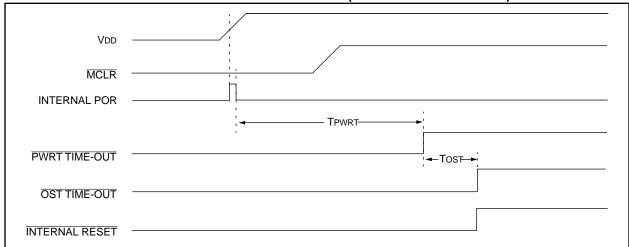


FIGURE 9-10: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

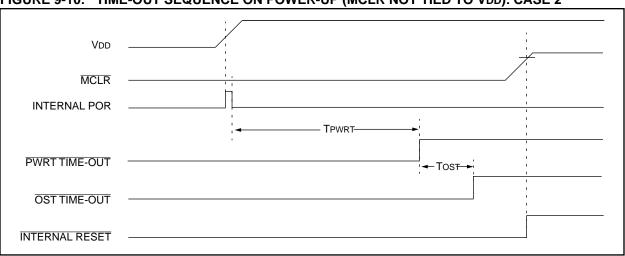


FIGURE 9-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

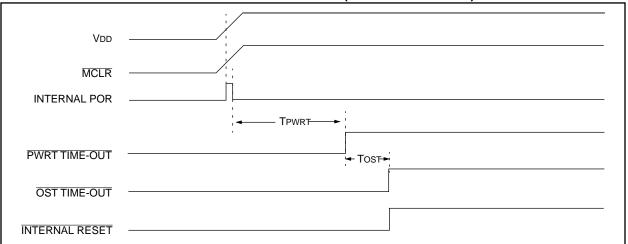
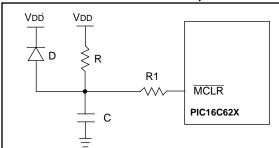
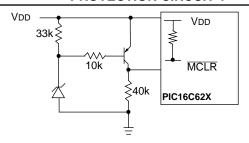


FIGURE 9-12: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



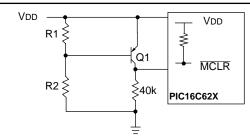
- Note 1: External power-on reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
 - 2: $< 40 \text{ k}\Omega$ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
 - 3: $R1 = 100\Omega$ to 1 $k\Omega$ will limit any current flowing into \overline{MCLR} from external capacitor C in the event of \overline{MCLR}/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

FIGURE 9-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



- Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.
 - 2: Internal Brown-out Reset circuitry should be disabled when using this circuit

FIGURE 9-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD X} \frac{R1}{R1 + R2} = 0.7 V$$

- 2: Internal brown-out reset should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistor.

9.5 Interrupts

The PIC16C62X has 4 sources of interrupt:

- · External interrupt RB0/INT
- TMR0 overflow interrupt
- · PortB change interrupts (pins RB7:RB4)
- · Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits interrupt routine as well as sets the GIE bit, which re-enable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

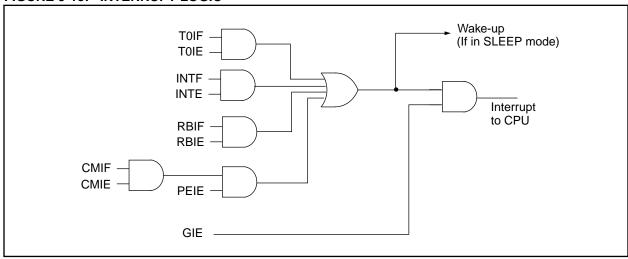
When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of

the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 9-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

- Note 1: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.
 - 2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a NOP in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

FIGURE 9-15: INTERRUPT LOGIC



9.5.1 **RB0/INT INTERRUPT**

External interrupt on RB0/INT pin is edge triggered: either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP and Figure 9-18 for timing of wake-up from SLEEP through RB0/INT interrupt.

9.5.2 TMR0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can enabled/disabled by setting/clearing (INTCON<5>) bit. For operation of the Timer0 module, see Section 6.0.

9.5.3 PORTB INTERRUPT

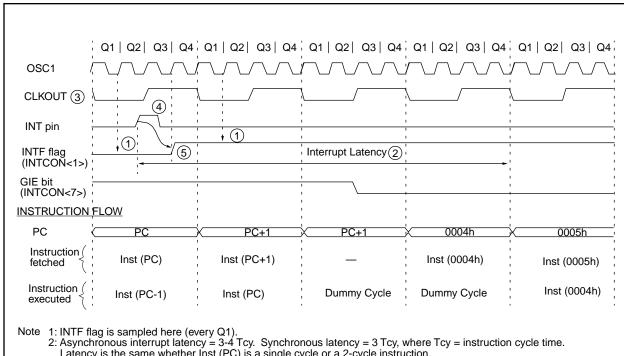
An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note: If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

9.5.4 COMPARATOR INTERRUPT

See Section 7.6 for complete description of comparator interrupts.

FIGURE 9-16: INT PIN INTERRUPT TIMING



- Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.
- 3: CLKOUT is available only in RC oscillator mode. 4: For minimum width of INT pulse, refer to AC specs
- 5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

TABLE 9-8: SUMMARY OF INTERRUPT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other resets ⁽¹⁾
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	_	CMIF	_	-	_	_	_	_	-0	-0
8Ch	PIE1	_	CMIE	_	_	_	_	_	_	-0	-0
Note1: Of	Note1: Other (non power-up) resets include MCLR reset, Brown-out Reset and Watchdog Timer Reset during normal operation.										

9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt e.g. W register and STATUS register. This will have to be implemented in software.

Example 9-1 stores and restores the STATUS and W registers. The user register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS_TEMP, must be defined in Bank 0. The Example 9-1:

- · Stores the W register
- Stores the STATUS register in Bank 0
- · Executes the ISR code
- Restores the STATUS (and bank select bit register)
- · Restores the W register

EXAMPLE 9-1: SAVING THE STATUS AND W REGISTERS IN RAM

MOVWF	W_TEMP	<pre>;copy W to temp register, ;could be in either bank</pre>
SWAPF	STATUS,W	;swap status to be saved into W
BCF	STATUS, RPO	<pre>;change to bank 0 regardless ;of current bank</pre>
MOVWF	STATUS_TEMP	<pre>;save status to bank 0 ;register</pre>
:		
:	(ISR)	
:		
SWAPF	STATUS_TEMP,W	<pre>;swap STATUS_TEMP register ;into W, sets bank to original ;state</pre>
MOVWF	STATUS	;move W into STATUS register
SWAPF	W_TEMP,F	;swap W_TEMP
SWAPF	W_TEMP,W	swap W_TEMP into W

9.7 Watchdog Timer (WDT)

The watchdog timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the CLKIN pin. That means that the WDT will run, even if the clock on the OSC1 and OSC2 pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming the configuration bit WDTE as clear (Section 9.1).

9.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

9.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

FIGURE 9-17: WATCHDOG TIMER BLOCK DIAGRAM

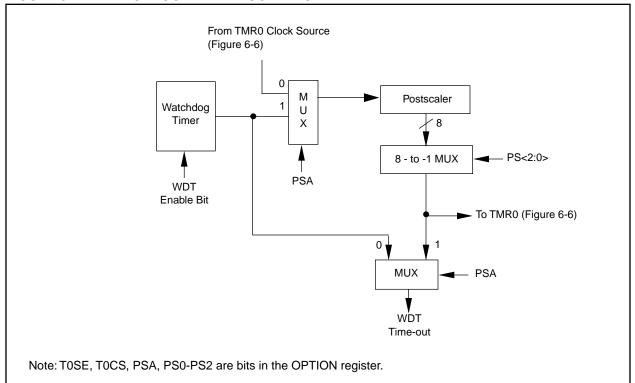


TABLE 9-9: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits		BOREN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.

Note: – = Unimplemented location, read as "0"

+ = Reserved for future use

9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the \overline{PD} bit in the STATUS register is cleared, the \overline{TO} bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD, or Vss, with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or Vss for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note: It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- External reset input on MCLR pin
- Watchdog Timer Wake-up (if WDT was enabled)
- Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

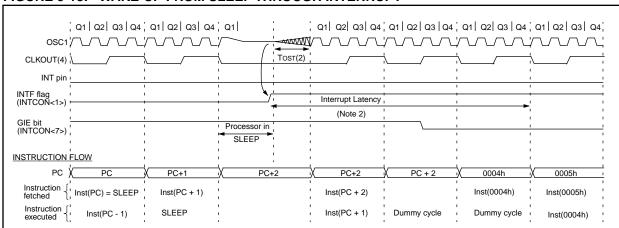
The first event will cause a device reset. The two latter events are considered a continuation of program execution. The $\overline{10}$ and \overline{PD} bits in the STATUS register can be used to determine the cause of device reset. \overline{PD} bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{10}$ bit is cleared if WDT Wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wakeup from sleep. The sleep instruction is completely executed.

The WDT is cleared when the device wakes-up from sleep, regardless of the source of wake-up.

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP oscillator mode assumed.

- 2: Tost = 1024Tosc (drawing not to scale) This delay will not be there for RC osc mode.
- 3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in these osc modes, but shown here for timing reference.

9.9 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

9.10 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. Only the least significant 4 bits of the ID locations are used.

9.11 In-Circuit Serial Programming

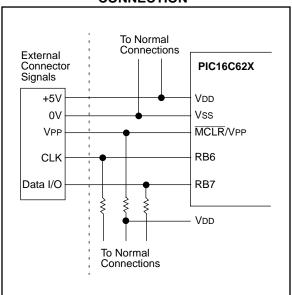
The PIC16C62X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the RB6 and RB7 pins low while raising the MCLR (VPP) pin from VIL to VIHH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X/9XX Programming Specifications (#DS30228).

A typical in-circuit serial programming connection is shown in Figure 9-19.

FIGURE 9-19: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



10.0 INSTRUCTION SET SUMMARY

Each PIC16C62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C62X instruction set summary in Table 10-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
х	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
()	Contents
\rightarrow	Assigned to
<>	Register bit field
€	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- Byte-oriented operations
- · Bit-oriented operations
- Literal and control operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs . If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs .

Table 10-1 lists the instructions recognized by the MPASM assembler.

Figure 10-1 shows the three general formats that the instructions can have.

Note: To maintain upward compatibility with future PICmicro™ products, <u>do not use</u> the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

Oxhl

where h signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS

INST	RUC	LIOI	NS	
Byte-oriented file reg	gister o	oerati	ions	_
	87	6		0
OPCODE	d		f (FILE #)	
d = 0 for destination W d = 1 for destination f f = 7-bit file register address				
Bit-oriented file regis	ter ope	ratio	ns	
13 1	0 9	7	6	0
OPCODE	b (BI	T #)	f (FILE #)	
Literal and control o	peratio	ns		
13	8	7		0
OPCODE			k (literal)	
k = 8-bit immediate value CALL and GOTO instructions only				
	0	O. II.y		0
OPCODE	U	k (literal)	\Box
k = 11-bit immediate value				

PIC16C62X

TABLE 10-2: PIC16C62X INSTRUCTION SET

Mnemonic,		Description	Cycles	14-Bit Opcode		Status	Notes		
Operands				MSb			LSb	Affected	
BYTE-ORIE	NTED	FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0000	0011	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100		ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110		ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIEN	TED FIL	E REGISTER OPERATIONS		•					
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL A	ND CO	NTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	
		I						1	

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

^{2:} If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

^{3:} If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

10.1 <u>Instruction Descriptions</u>

ADDLW	Add Literal and W					
Syntax:	[label] ADDLW k					
Operands:	$0 \le k \le 255$					
Operation:	$(W) + k \to (W)$					
Status Affected:	C, DC, Z					
Encoding:	11 111x kkkk kkkk					
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.					
Words:	1					
Cycles:	1					
Example	ADDLW 0x15					
	Before Instruction W = 0x10 After Instruction W = 0x25					

ANDLW	AND Literal with W					
Syntax:	[label] ANDLW k					
Operands:	$0 \le k \le 255$					
Operation:	(W) .AND. $(k) \rightarrow (W)$					
Status Affected:	Z					
Encoding:	11 1001 kkkk kkkk					
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.					
Words:	1					
Cycles:	1					
Example	ANDLW 0x5F					
	Before Instruction W = 0xA3 After Instruction W = 0x03					

ADDWF	Add W a	nd f			
Syntax:	[label] I	ADDWF	f,d		
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	$(W) + (f) \to (dest)$				
Status Affected:	C, DC, Z				
Encoding:	00	0111	dfff	ffff	
Description:	with regist stored in t	er 'f'. If 'd' he W regi	the W reg is 0 the re ster. If 'd' is c in registe	sult is 1 the	
Words:	1				
Cycles:	1				
Example	ADDWF	FSR,	0		
	After Inst	W = FSR =	0x17 0xC2 0xD9		
		vv –	0,00		

FSR =

0xC2

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .AND. (f) \rightarrow (dest)
Status Affected:	Z
Encoding:	00 0101 dfff ffff
Description:	AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	ANDWF FSR, 1
	Before Instruction $W = 0x17$ $FSR = 0xC2$ After Instruction $W = 0x17$ $FSR = 0x02$

BCF	Bit Clear f	BTFSC	Bit Test, S
Syntax:	[label] BCF f,b	Syntax:	[label] BT
Operands:	$0 \le f \le 127$ $0 \le b \le 7$	Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$0 \rightarrow (f < b >)$	Operation:	skip if (f <b< td=""></b<>
Status Affected:	None	Status Affected:	None
Encoding:	01 00bb bfff ffff	Encoding:	01
Description: Words: Cycles: Example	Bit 'b' in register 'f' is cleared. 1 1 BCF FLAG_REG, 7 Before Instruction	Description:	If bit 'b' in reinstruction is instruction is If bit 'b' is '0 fetched duri execution is executed instruction.
	FLAG_REG = 0xC7 After Instruction FLAG_REG = 0x47	Words: Cycles: Example	1 1(2) HERE FALSE TRUE

BSF	Bit Set f			
Syntax:	[label] BSF f,b			
Operands:	$0 \le f \le 127$ $0 \le b \le 7$			
Operation:	$1 \rightarrow (f < b)$	>)		
Status Affected:	None			
Encoding:	01 01bb bfff		bfff	ffff
Description:	Bit 'b' in register 'f' is set.			
Words:	1			
Cycles:	1			
Example	BSF	FLAG_F	REG, 7	
	After Inst	FLAG_RE	EG = 0x0A $EG = 0x8A$	

BTFSC	Bit Test,	Skip if Cl	ear	
Syntax:	[label] BTFSC f,b			
Operands:	$0 \le f \le 127$ $0 \le b \le 7$			
Operation:	skip if $(f < b >) = 0$			
Status Affected:	None			
Encoding:	01	10bb	bfff	ffff
Description:	instruction If bit 'b' is ' fetched du execution executed i	register 'f' is is skipped. 0' then the uring the curing the curis discarded nstead, mainstruction.	next instru rent instru d, and a No	ction ction
Words:	1			
Cycles:	1(2)			
Example	HERE FALSE TRUE		FLAG,1 PROCESS_	_CODE
	After Inst	PC = a ruction if FLAG<1> PC = a if FLAG<1>	= 0, address T	ERE RUE ALSE

BTFSS	Bit Test f	, Skip if S	et	
Syntax:	[label] BTFSS f,b			
Operands:	$0 \le f \le 127$ $0 \le b < 7$			
Operation:	skip if (f<	b>) = 1		
Status Affected:	None			
Encoding:	01	11bb	bfff	ffff
Description:	If bit 'b' in register 'f' is '1' then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a two-cycle instruction.			
Words:	1			
Cycles:	1(2)			
Example	HERE FALSE TRUE		FLAG,1 PROCESS_	_CODE
	Before In		ddress H	ERE
	After Instruction			
		if FLAG<1>		
		_	address F.	ALSE
		if FLAG<1> PC = = 6	·= ı, address T	RUE

CLRF	Clear f
Syntax:	[label] CLRF f
Operands:	$0 \le f \le 127$
Operation:	$\begin{array}{l} 00h \rightarrow (f) \\ 1 \rightarrow Z \end{array}$
Status Affected:	Z
Encoding:	00 0001 1fff ffff
Description:	The contents of register 'f' are cleared and the Z bit is set.
Words:	1
Cycles:	1
Example	CLRF FLAG_REG
	Before Instruction
	FLAG_REG = 0x5A
	After Instruction FLAG_REG = 0x00
	Z = 1

CALL	Call Subroutine		
Syntax:	[label] CALL k		
Operands:	$0 \le k \le 2047$		
Operation:	(PC)+ 1 \rightarrow TOS, k \rightarrow PC<10:0>, (PCLATH<4:3>) \rightarrow PC<12:11>		
Status Affected:	None		
Encoding:	10 0kkk kkkk kkkk		
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.		
Words:	1		
Cycles:	2		
Example	HERE CALL THERE		
	Before Instruction PC = Address HERE After Instruction		

PC = Address THERE
TOS = Address HERE+1

CLRW	Clear W
Syntax:	[label] CLRW
Operands:	None
Operation:	$\begin{array}{l} 00h \rightarrow (W) \\ 1 \rightarrow Z \end{array}$
Status Affected:	Z
Encoding:	00 0001 0000 0011
Description:	W register is cleared. Zero bit (Z) is set.
Words:	1
Cycles:	1
Example	CLRW
	Before Instruction
	W = 0x5A After Instruction
	W = 0x00
	Z = 1

CLRWDT	Clear Watchdog Timer
Syntax:	[label] CLRWDT
Operands:	None
Operation:	$\begin{array}{l} 00h \to WDT \\ 0 \to WDT \text{ prescaler,} \\ 1 \to \overline{TO} \\ 1 \to \overline{PD} \end{array}$
Status Affected:	TO, PD
Encoding:	00 0000 0110 0100
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits TO and PD are set.
Words:	1
Cycles:	1
Example	CLRWDT
	Before Instruction
	PD = 1

DECF	Decrement f	
Syntax:	[label] DECF f,d	
Operands:	$0 \le f \le 127$ $d \in [0,1]$	
Operation:	(f) - 1 \rightarrow (dest)	
Status Affected:	Z	
Encoding:	00 0011 dfff	ffff
Description:	Decrement register 'f'. If 'd' is 0 result is stored in the W register is 1 the result is stored back in re'f'.	the r. If 'd' egister
Words:	1	
Cycles:	1	
Example	DECF CNT, 1	
	Before Instruction $\begin{array}{rcl} CNT & = & 0x01\\ Z & = & 0 \end{array}$ $\begin{array}{rcl} After Instruction & & & 0x00\\ CNT & = & 0x00\\ Z & = & 1 \end{array}$	

COMF	Complen	nent f			
Syntax:	[label]	COMF	f,d		
Operands:	$0 \le f \le 12$ $d \in [0,1]$	7			
Operation:	$(\bar{f}) \rightarrow (des$	st)			
Status Affected:	Z				
Encoding:	00	1001	dff	f	ffff
Description:	The contercompleme stored in V stored back	nted. If 'd' V. If 'd' is ´	is 0 t I the	the re result	sult is is
Words:	1				
Cycles:	1				
Example	COMF	REG	1,0		
	After Inst	REG1	= = =	0x13 0x13 0xEC	

[label] $0 \le f \le 12$ $d \in [0,1]$		Z f,d	
d ∈ [0,1]	7		
(f) _ 1 \ \			
$(1) - 1 \rightarrow ($	(dest);	skip if re	esult = 0
None			
0.0	1011	dfff	ffff
decremente placed in the result is pla If the result which is alr NOP is exe	ed. If 'd' is ne W regis aced back is 0, the eady fetc cuted ins	0 the resu ster. If 'd' is in register next instruc hed, is disc tead makin	1 the 'f'. etion, earded. A
1			
1(2)			
HERE CONTINI	GOTO		Γ, 1 OP
00111111	•		
PC After Instr CNT if CNT PC if CNT	= ad ruction = CN = 0, = ad ≠ 0,	dress here IT - 1 dress CON	FINUE
	The contendecremente placed in the result is placed in the result which is alm NOP is exet two-cycle in 1 (2) HERE CONTINUE Before Inst. CNT if CNT PC	The contents of regis decremented. If 'd' is placed in the W regis result is placed back if the result is 0, the which is already fetc NOP is executed ins two-cycle instruction 1 1(2) HERE DECF GOTO CONTINUE • Before Instruction PC = add After Instruction CNT = CN if CNT = 0, PC = add if CNT ≠ 0,	The contents of register 'f' are decremented. If 'd' is 0 the resu placed in the W register. If 'd' is result is placed back in register If the result is 0, the next instruct which is already fetched, is disc NOP is executed instead makin two-cycle instruction. 1 1(2) HERE DECFSZ CNT. GOTO LOC CONTINUE • • Before Instruction PC = address HERE After Instruction CNT = CNT - 1 if CNT = 0, PC = address CONT. if CNT ≠ 0,

GOTO	Unconditional Branch
Syntax:	[label] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	$k \rightarrow PC<10:0>$ PCLATH<4:3> \rightarrow PC<12:11>
Status Affected:	None
Encoding:	10 1kkk kkkk kkkk
Description:	GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.
Words:	1
Cycles:	2
Example	GOTO THERE
	After Instruction PC = Address THERE

INCFSZ	Increment f, Skip if 0				
Syntax:	[label] I	NCFSZ	f,d		
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	$(f) + 1 \rightarrow (e)$	dest), s	kip if resu	ult = 0	
Status Affected:	None				
Encoding:	0.0	1111	dfff	ffff	
Description:	The content incremented placed in the result is plan If the result which is alrea A NOP is exal a two-cycle	d. If 'd' is e W regiced back is 0, the eady fetoxecuted	O the resu ster. If 'd' is o in registe next instruched, is dis instead ma	ult is s 1 the er 'f'.	
Words:	1				
Cycles:	1(2)				
Example	HERE CONTINUE	INCFS GOTO •	-	NT, 1 OOP	
	Before Ins	truction			
	PC = After Instru CNT = if CNT= PC = if CNT≠ PC =	uction = CN 0, = add	Iress HERE T + 1 Iress CONT	TINUE	

INCF	Increment f				
Syntax:	[label] INCF f,d				
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	$(f) + 1 \rightarrow (dest)$				
Status Affected:	Z				
Encoding:	00 1010 dfff ffff				
Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.				
Words:	1				
Cycles:	1				
Example	INCF CNT, 1				
	Before Instruction CNT = 0xFF Z = 0 After Instruction CNT = 0x00 Z = 1				

IORLW	Inclusive OR Literal with W
Syntax:	[label] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. $k \rightarrow$ (W)
Status Affected:	Z
Encoding:	11 1000 kkkk kkkk
Description:	The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example	IORLW 0x35
	Before Instruction W = 0x9A After Instruction W = 0xBF Z = 1

PIC16C62X

IORWF	Inclusive OR W with f				
Syntax:	[label]	IORWF	f,d		
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27			
Operation:	(W) .OR.	$(f) \rightarrow (de)$	est)		
Status Affected:	Z				
Encoding:	00	0100	dff	f	ffff
Description:	Inclusive (register 'f'. in the W re placed ba	If 'd' is 0 t egister. If '	he re d' is 1	sult is I the r	placed
Words:	1				
Cycles:	1				
Example	IORWF		RESU	LT,	0
	After Inst	RESULT W	=	0x13 0x91 0x13 0x93 1	

MOVF	Move f				
Syntax:	[label]	MOVF	f,d		
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	(f) \rightarrow (de:	st)			
Status Affected:	Z				
Encoding:	00	1000	dfff	ffff	
Description:	The conter a destinati status of d register. If register f it file registe affected.	on depend $d = 0$, $d = 1$, the self. $d = 1$	dent upon destination destination is useful t	the n is W n is file to test a	
Words:	1				
Cycles:	1				
Example			0 ue in FSR r	egister	

MOVLW	Move Literal to W			
Syntax:	[label] MOVLW k			
Operands:	$0 \le k \le 255$			
Operation:	$k \to (W)$			
Status Affected:	None			
Encoding:	11	00xx	kkkk	kkkk
Description:	The eight bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.			
Words:	1			
Cycles:	1			
Example	MOVLW	0x5A		
	After Inst	ruction W =	0x5A	

MOVWF	Move W to f				
Syntax:	[label] MOVWF f				
Operands:	$0 \le f \le 127$				
Operation:	$(W) \rightarrow (f)$)			
Status Affected:	None				
Encoding:	00	0000	1ff	f	ffff
Description:	Move data from W register to register 'f'.				
Words:	1				
Cycles:	1				
Example	MOVWF	OPT	CION		
	After Inst	OPTION W	=	0xFF 0x4F 0x4F 0x4F	:

NOP	No Operation			
Syntax:	[label]	NOP		
Operands:	None			
Operation:	No opera	ition		
Status Affected:	None			
Encoding:	0.0	0000	0xx0	0000
Description:	No operati	ion.		
Words:	1			
Cycles:	1			
Example	NOP			

RETFIE	Return from Interrupt				
Syntax:	[label]	RETFIE			
Operands:	None				
Operation:	$TOS \rightarrow PC,$ $1 \rightarrow GIE$				
Status Affected:	None				
Encoding:	00	0000	0000	1001	
Description:	Return from and Top of the PC. Into setting Gloud GIE (INTC instruction)	Stack (To terrupts a bbal Interr ON<7>).	OS) is load re enabled upt Enable	led in by bit,	
Words:	1				
Cycles:	2				
Example	RETFIE				
		rrupt PC = GIE =	TOS 1		

OPTION	Load Option Register			
Syntax:	[label]	OPTIO	٧	
Operands:	None			
Operation:	$(W) \to OPTION$			
Status Affected:	None			
Encoding:	0.0	0000	0110	0010
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.			
Words:	1			
Cycles:	1			
Example				
	with futu	re PICmi	rd compa cro™ prod struction.	ducts,

RETLW	Return with Literal in W			
Syntax:	[label]	RETLW	k	
Operands:	$0 \le k \le 25$	55		
Operation:	$\begin{array}{l} k \rightarrow \text{(W);} \\ \text{TOS} \rightarrow P \end{array}$	С		
Status Affected:	None			
Encoding:	11	01xx	kkkk	kkkk
Description:	The W regi bit literal 'k' loaded fron return addr instruction.	'. The pro n the top ress). Thi	gram cour	nter is ck (the
Words:	1			
Cycles:	2			
Example	call Table value	;of:	contains t fset value now has ta	2
TABLE	ADDWF PC RETLW k1 RETLW k2	;Beq;	= offset gin table nd of tabl	.e
	Before Ins	struction	1	
		N =	0x07	
	After Instr		value of k	8

RETURN	Return from Subroutine			
Syntax:	[label]	RETUR	N	
Operands:	None			
Operation:	$TOS \to PC$			
Status Affected:	None			
Encoding:	00	0000	0000	1000
Description:	Return fro POPed an is loaded i This is a to	d the top nto the pr	of the stac	k (TOS) inter.
Words:	1			
Cycles:	2			
Example	RETURN			
	After Inte	rrupt PC =	TOS	

RRF	Rotate Right f through Carry					
Syntax:	[label] RRF	f,d				
Operands:	$0 \le f \le 127$ $d \in [0,1]$					
Operation:	See description	n below				
Status Affected:	С					
Encoding:	00 1100	0 dfff ffff				
Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.					
	C Register f					
Words:	1					
Cycles:	1					
Example	RRF	REG1,0				
	Before Instruction					
	REG1	= 1110 0110				
	C	= 0				
	After Instruction					
	REG1 W	= 1110 0110 = 0111 0011				
	C	= 0111 0011				

RLF	Rotate Left f through Carry				
Syntax:	[label]	RLF	f,d		
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27			
Operation:	See desc	ription b	elow	,	
Status Affected:	С				
Encoding:	00	1101	df:	Ef	ffff
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'. Register f				
Words:	1				
Cycles:	1				
Example	RLF REG1,0				
	After Inst	REG1 C	= = = = =	1110 0 1110 1	0 0110

SLEEP				
Syntax:	[label] SLEEP			
Operands:	None			
Operation:	$\begin{array}{l} \text{00h} \rightarrow \text{WDT,} \\ \text{0} \rightarrow \text{WDT prescaler,} \\ \text{1} \rightarrow \overline{\text{TO}}, \\ \text{0} \rightarrow \overline{\text{PD}} \end{array}$			
Status Affected:	TO, PD			
Encoding:	00 0000 0110 0011			
Description:	The power-down status bit, PD is cleared. Time-out status bit, TO is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See Section 9.8 for more details.			
Words:	1			
Cycles:	1			
Example:	SLEEP			

SUBLW	Subtract W from Literal	SUBWF	Subtract W from f		
Syntax:	[label] SUBLW k	Syntax:	[label] SUBWF f,d		
Operands:	$0 \le k \le 255$	Operands:	$0 \le f \le 127$		
Operation:	$k - (W) \rightarrow (W)$		d ∈ [0,1]		
Status	C, DC, Z	Operation:	$(f) - (W) \to (dest)$		
Affected:		Status	C, DC, Z		
Encoding:	11 110x kkkk kkkk	Affected:	00 0010 1555 5555		
Description:	The W register is subtracted (2's complement method) from the eight bit literal	Encoding:	00 0010 dfff ffff		
	'k'. The result is placed in the W register.	Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0 the		
Words:	1		result is stored in the W register. If 'd' is 1		
Cycles:	1	Words:	the result is stored back in register 'f'. 1		
Example 1:	SUBLW 0x02	Cycles:	1		
	Before Instruction	Example 1:	SUBWF REG1,1		
	W = 1	Liample 1.	Before Instruction		
	C = ?		REG1 = 3		
	After Instruction		W = 2		
	W = 1 C = 1; result is posi-		C = ?		
	tive		After Instruction		
Example 2:	Before Instruction		REG1 = 1 W = 2		
	W = 2		C = 1; result is positive		
	C = ?	Example 2:	Before Instruction		
	After Instruction		REG1 = 2		
	W = 0 C = 1; result is zero		W = 2 C = ?		
Example 3:	Before Instruction		After Instruction		
	W = 3		REG1 = 0		
	C = ?		W = 2		
	After Instruction	F	C = 1; result is zero		
	W = 0xFF C = 0; result is nega-	Example 3:	Before Instruction		
	tive		REG1 = 1 W = 2		
			C = ?		
			After Instruction		
			$ \begin{array}{rcl} REG1 & = & 0xFF \\ W & = & 2 \end{array} $		
			W = 2 C = 0; result is negative		

SWAPF	Swap Nibbles in f				
Syntax:	[label] SWAPF f,d				
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	$(f<3:0>) \rightarrow (dest<7:4>),$ $(f<7:4>) \rightarrow (dest<3:0>)$				
Status Affected:	None				
Encoding:	00	1110	dfff	ffff	
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.				
Words:	1				
Cycles:	1				
Example	SWAPF	REG,	0		
	Before Instruction				
		REG1	= (xA5	
	After Inst	ruction			
		REG1	= ()xA5	
		W	= ()x5A	

XORLW	Exclusive OR Literal with W			
Syntax:	[label] XORLW k			
Operands:	$0 \le k \le 255$			
Operation:	(W) .XOR. $k \rightarrow$ (W)			
Status Affected:	Z			
Encoding:	11 1010 kkkk kkkk			
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.			
Words:	1			
Cycles:	1			
Example:	XORLW 0xAF			
	Before Instruction			
	W = 0xB5			
	After Instruction			
	W = 0x1A			

TRIS	Load TRIS Register			
Syntax:	[label] TRIS f			
Operands:	$5 \le f \le 7$			
Operation:	$(W) \to TRIS \; register \; f;$			
Status Affected:	None			
Encoding:	00 0000 0110 Offf			
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.			
Words:	1			
Cycles: Example	1			
	To maintain upward compatibility with future PICmicro™ products, do not use this instruction.			

XORWF	Exclusive OR W with f				
Syntax:	[label]	XORWF	f,d		
Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	(W) .XOF	$R. (f) \rightarrow (c$	dest)		
Status Affected:	Z				
Encoding:	00	0110	dff	f	ffff
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example	XORWF	REG	1		
	Before Instruction				
		REG W	=	0x/ 0xl	••
	After Instruction				
		REG W	= =	0x′ 0xl	

11.0 DEVELOPMENT SUPPORT

11.1 Development Tools

The PICmicro[™] microcontrollers are supported with a full range of hardware and software development tools:

- MPLAB™-ICE Real-Time In-Circuit Emulator
- ICEPIC™ Low-Cost PIC16C5X and PIC16CXXX In-Circuit Emulator
- PRO MATE® II Universal Programmer
- PICSTART[®] Plus Entry-Level Prototype Programmer
- SIMICE
- PICDEM-1 Low-Cost Demonstration Board
- PICDEM-2 Low-Cost Demonstration Board
- PICDEM-3 Low-Cost Demonstration Board
- MPASM Assembler
- MPLAB™ SIM Software Simulator
- MPLAB-C17 (C Compiler)
- Fuzzy Logic Development System (fuzzyTECH[®]–MP)
- KEELOQ[®] Evaluation Kits and Programmer

11.2 MPLAB-ICE: High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB-ICE Universal In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers (MCUs). MPLAB-ICE is supplied with the MPLAB Integrated Development Environment (IDE), which allows editing, "make" and download, and source debugging from a single environment.

Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB-ICE allows expansion to support all new Microchip microcontrollers.

The MPLAB-ICE Emulator System has been designed as a real-time emulation system with advanced features that are generally found on more expensive development tools. The PC compatible 386 (and higher) machine platform and Microsoft Windows[®] 3.x or Windows 95 environment were chosen to best make these features available to you, the end user.

MPLAB-ICE is available in two versions. MPLAB-ICE 1000 is a basic, low-cost emulator system with simple trace capabilities. It shares processor modules with the MPLAB-ICE 2000. This is a full-featured emulator system with enhanced trace, trigger, and data monitoring features. Both systems will operate across the entire operating speed reange of the PICmicro MCU.

11.3 <u>ICEPIC: Low-Cost PICmicro™</u> In-Circuit Emulator

ICEPIC is a low-cost in-circuit emulator solution for the Microchip PIC12CXXX, PIC16C5X and PIC16CXXX families of 8-bit OTP microcontrollers.

ICEPIC is designed to operate on PC-compatible machines ranging from 386 through Pentium™ based machines under Windows 3.x, Windows 95, or Windows NT environment. ICEPIC features real time, non-intrusive emulation.

11.4 PRO MATE II: Universal Programmer

The PRO MATE II Universal Programmer is a full-featured programmer capable of operating in stand-alone mode as well as PC-hosted mode. PRO MATE II is CE compliant.

The PRO MATE II has programmable VDD and VPP supplies which allows it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for displaying error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In standalone mode the PRO MATE II can read, verify or program PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices. It can also set configuration and code-protect bits in this mode.

11.5 <u>PICSTART Plus Entry Level</u> <u>Development System</u>

The PICSTART programmer is an easy-to-use, low-cost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. PICSTART Plus is not recommended for production programming.

PICSTART Plus supports all PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices with up to 40 pins. Larger pin count devices such as the PIC16C923, PIC16C924 and PIC17C756 may be supported with an adapter socket. PICSTART Plus is CE compliant.

11.6 <u>SIMICE Entry-Level Hardware</u> Simulator

SIMICE is an entry-level hardware development system designed to operate in a PC-based environment with Microchip's simulator MPLAB™-SIM. Both SIM-ICE and MPLAB-SIM run under Microchip Technology's MPLAB Integrated Development Environment (IDE) software. Specifically, SIMICE provides hardware simulation for Microchip's PIC12C5XX, PIC12CE5XX, and PIC16C5X families of PICmicro™ 8-bit microcontrollers. SIMICE works in conjunction with MPLAB-SIM to provide non-real-time I/O port emulation. SIMICE enables a developer to run simulator code for driving the target system. In addition, the target system can provide input to the simulator code. This capability allows for simple and interactive debugging without having to manually generate MPLAB-SIM stimulus files. SIMICE is a valuable debugging tool for entrylevel system development.

11.7 <u>PICDEM-1 Low-Cost PICmicro</u> Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the MPLAB-ICE emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

11.8 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I²C bus and separate headers for connection to an LCD module and a keypad.

11.9 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

11.10 MPLAB Integrated Development Environment Software

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- · A full featured editor
- · Three operating modes
 - editor
 - emulator
 - simulator
- · A project manager
- · Customizable tool bar and key mapping
- A status bar with project information
- · Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PICmicro tools (automatically updates all project information)
- · Debug using:
 - source files
 - absolute listing file

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

11.11 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PC-hosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from MPLAB-ICE, Microchip's Universal Emulator System.

MPASM has the following features to assist in developing software for specific use applications.

- Provides translation of Assembler source code to object code for all Microchip microcontrollers.
- · Macro assembly capability.
- Produces all the files (Object, Listing, Symbol, and special) required for symbolic debug with Microchip's emulator systems.
- Supports Hex (default), Decimal and Octal source and listing formats.

MPASM provides a rich directive language to support programming of the PICmicro. Directives are helpful in making the development of your assemble source code shorter and more maintainable.

11.12 Software Simulator (MPLAB-SIM)

The MPLAB-SIM Software Simulator allows code development in a PC host environment. It allows the user to simulate the PICmicro series microcontrollers on an instruction level. On any given instruction, the user may examine or modify any of the data areas or provide external stimulus to any of the pins. The input/output radix can be set by the user and the execution can be performed in; single step, execute until break, or in a trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C17 and MPASM. The Software Simulator offers the low cost flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

11.13 MPLAB-C17 Compiler

The MPLAB-C17 Code Development System is a complete ANSI 'C' compiler and integrated development environment for Microchip's PIC17CXXX family of microcontrollers. The compiler provides powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compiler provides symbol information that is compatible with the MPLAB IDE memory display.

11.14 <u>Fuzzy Logic Development System</u> (fuzzyTECH-MP)

fuzzyTECH-MP fuzzy logic development tool is available in two versions - a low cost introductory version, MP Explorer, for designers to gain a comprehensive working knowledge of fuzzy logic system design; and a full-featured version, fuzzyTECH-MP, Edition for implementing more complex systems.

Both versions include Microchip's *fuzzy*LAB™ demonstration board for hands-on experience with fuzzy logic systems implementation.

11.15 <u>SEEVAL® Evaluation and Programming System</u>

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials™ and secure serials. The Total Endurance™ Disk is included to aid in trade-off analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

11.16 <u>KEELoq® Evaluation and</u> <u>Programming Tools</u>

KEELOQ evaluation and programming tools support Microchips HCS Secure Data Products. The HCS evaluation kit includes an LCD display to show changing codes, a decoder to decode transmissions, and a programming interface to program test transmitters.

	PIC12C5XX	PIC14000	PIC16C5X	PIC16CXXX	PIC16C6X	PIC16C7XX	PIC16C8X	PIC16C9XX	PIC17C4X	PIC17C7XX	24CXX 25CXX 93CXX	HCS200 HCS300 HCS301	TABLE
MPLAB™-ICE ICEPIC™ Low-Cost In-Circuit Emulator	✓	✓	√	*	✓	√	✓	√	✓	~			11-1: DE
ICEPIC™ Low-Cost In-Circuit Emulator			✓	√	✓	✓	✓	✓					VELC
MPLAB™ Integrated Development Environment	*	✓	√	✓	√	✓	√	✓	✓	✓			DEVELOPMENT TOOLS
8 MPLAB™ C17* Compiler									✓	✓			00
fuzzyTECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	✓	✓	✓	√	√	✓	√	✓	✓				S FROM MICROCHIP
Total Endurance™ Software Model											✓		M CF
PICSTART®Plus Low-Cost Universal Dev. Kit	√	✓	✓	✓	√	✓	√	✓	✓	✓			OCHIE
PRO MATE [®] II Universal Programmer	✓	✓	✓	✓	✓	✓	√	✓	√	✓	✓	✓	
KEELOQ [®] Programmer												✓	
SEEVAL [®] Designers Kit											✓		
SIMICE	/		✓										1
Ø PICDEM-14A		√											†
ច្ច PICDEM-1			✓	√			✓		✓				1
PICDEM-2					✓	✓							1
PICDEM-3								✓					1
KEELOQ® Evaluation Kit												√	
KEELOQ Transponder Kit												✓	

NOTES:

12.0 89ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Note:

Ambient Temperature under bias	40° to +125°C
Storage Temperature	65° to +150°C
Voltage on any pin with respect to Vss (except VDD and MCLR)	0.6V to VDD +0.6V
Voltage on VDD with respect to Vss	0 to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0 to +14V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of Vss pin	300 mA
Maximum Current into VDD pin	250 mA
Input Clamp Current, Iικ (VI <0 or VI> VDD)	±20 mA
Output Clamp Current, loκ (Vo <0 or Vo>VDD)	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	200 mA
Maximum Current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH) x IOH} + \sum (VOI x IOL)

† **NOTICE**: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note: Voltage spikes below Vss at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

Voltage spikes below Vss at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to Vss.

TABLE 12-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C62X-04	PIC16C62XA-04	PIC16C62X-20	PIC16C62XA-20	PIC16LC62X-04	PIC16C62X/JW	PIC16C62XA/JW
RC	VDD: 3.0V to 6.0V IDD: 3.3 mA max. @5.5V IPD: 20 µA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 3.3 mA max. @5.5V IPD: 20 μA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 1.8 mA typ. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 1.8 mA typ. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. @3.0V IPD: 0.7 μA typ. @3.0V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 3.3 mA max. @5.5V IPD: 20 μA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 3.3 mA max. @5.5V IPD: 20 µA max. @4.0V Freq: 4.0 MHz max.
XT	VDD: 3.0V to 6.0V IDD: 3.3 mA max. @5.5V IPD: 20 μA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 3.3 mA max. @5.5V IPD: 20 μA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 1.8 mA typ. @5.5V IPD: 1.0 µA typ. @4.5V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 1.8 mA typ. @5.5V IPD: 1.0 µA typ. @4.5V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. @3.0V IPD: 0.7 µA typ. @3.0V Freq: 4.0 MHz max.	VDD: 3.0V to 6.0V IDD: 3.3 mA max. @5.5V IPD: 20 μA max. @4.0V Freq: 4.0 MHz max.	VDD: 3.0V to 5.5V IDD: 3.3 mA max. @5.5V IPD: 20 µA max. @4.0V Freq: 4.0 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 9.0 mA typ. @5.5V IPD: 1.0 µA typ. @4.0V Freq: 4.0 MHz max.	VDD: 4.5V to 5.5V IDD: 3.5 mA typ. @5.5V IPD: 1.0 µA typ. @4.0V Freq: 4.0 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 20 MHz max.	VDD: 4.5V to 5.5V IDD: 7.5 mA max. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 20 MHz max.	N/A	VDD: 4.5V to 5.5V IDD: 20 mA max. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 20 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. @5.5V IPD: 1.0 μA typ. @4.5V Freq: 20 MHz max.
LP	VDD: 3.0V to 6.0V IDD: 35 μA typ. @32 kHz, 3.0V IPD: 1.0 μA typ. @4.0 V Freq: 200 kHz max.	VDD: 3.0V to 5.5V IDD: 35 μA typ. @32 kHz, 3.0V IPD: 1.0 μA typ. @4.0 V Freq: 200 kHz max.	N/A	N/A	VDD: 2.5V to 6.0V IDD: 32 μA max. @32 kHz, 3.0V IPD: 9.0 μA max. @3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 32 μA max. @32 kHz, 3.0V IPD: 9.0 μA Max. @3.0V Freq: 200 kHz max.	VDD: 3.0V to 5.5V IDD: 32 μA max. @32 kHz, 3.0V IPD: 9.0 μA Max. @3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that the specifications required.

12.1 DC CHARACTERISTICS: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended)

		Standard Operating Conditions (unless otherwise stated)					
		Operating temperature -40°C	≤ TA ≤	+85°C	for inc	dustrial	and
		0°C ≤ TA ≤ +70°C for commercial and				al and	
		−40°C	≤ TA ≤	+125°(C for e	xtende	d
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
D001 D001A	Vdd	Supply Voltage	3.0 4.5	-	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002	Vdr	RAM Data Retention Voltage (Note 1)	-	1.5*	-	V	Device in SLEEP mode
D003	Vpor	VDD start voltage to ensure Power-on Reset	_	Vss	_	V	See section on power-on reset for details
D004	Svdd	VDD rise rate to ensure Power-on Reset	0.05*	_	-	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7 3.7	4.0 4.0	4.3 4.4	V	BOREN configuration bit is cleared (Extended)
D010 D010A	ldd	Supply Current (Note 2)	_	1.8	3.3	mA μA	XT and RC osc configuration FOSC = 4 MHz, VDD = 5.5V, WDT disabled (Note 4) LP osc configuration, PIC16C62X-04 only
D013			_	9.0	20	mA	Fosc = 32 kHz, VDD = 4.0V, WDT disabled HS osc configuration Fosc = 20 MHz, VDD = 5.5V, WDT disabled
D020	lpd	Power Down Current (Note 3)	_	1.0	2.5 15	μΑ μΑ	VDD=4.0V, WDT disabled (125°C)
	Δlwdt	WDT Current (Note 5)	-	6.0	20 25	μA μA	VDD=4.0V (125°C)
D023	ΔIBOR	Brown-out Reset Current (Note 5) Comparator Current for each Com-	_	350	425	μΑ	BOR enabled, VDD = 5.0V
	ΔІСОМР	parator (Note 5) VREF Current (Note 5)	_		100	μΑ	VDD = 4.0V
	Δ IVREF		_		300	μΑ	VDD = 4.0V

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

- 3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in $k\Omega$.
- 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.2 DC CHARACTERISTICS: PIC16LC62X-04 (Commercial, Industrial)

		Standard Operating Condition	s (unle	ss othe	erwise	stated)		
		Operating temperature -40°C	\leq TA \leq	+85°C	for inc	lustrial	and		
		0°C ≤TA≤+70°C for commercial and							
		−40°C	≤ TA ≤	+125°C	C for e	xtended	d		
		Operating voltage VDD range as	descril	bed in D	OC spe	ec Table	e 12-1 and Table 12-2		
Param	Sym	Characteristic	Min Typ† Max Units			Units	Conditions		
No.									
D001	VDD	Supply Voltage	3.0	-	6.0	V	XT and RC osc configuration		
			2.5		6.0		LP osc configuration		
D002	VDR	RAM Data Retention Voltage (Note 1)	_	1.5*	_	V	Device in SLEEP mode		
D003	VPOR	VDD start voltage to ensure Power-on Reset	_	Vss	_	V	See section on Power-on Reset for details		
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	-	_	V/ms	See section on Power-on Reset for details		
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.3	V	BOREN configuration bit is cleared		
D010	IDD	Supply Current (Note 2)	_	1.4	2.5	mA	XT and RC osc configuration Fosc = 2.0 MHz, VDD = 3.0V, WDT disabled (Note 4)		
D010A			_	26	53	μА	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled		
D020	IPD	Power Down Current (Note 3)	_	0.7	2	μΑ	VDD=3.0V, WDT disabled		
	ΔIWDT	WDT Current (Note 5)	_	6.0	15	μΑ	VDD=3.0V		
D023	Δ IBOR	Brown-out Reset Current (Note 5)	_	350	425	μА	BOR enabled, VDD = 5.0V		
	ΔICOMP	Comparator Current for each Comparator (Note 5)	_		100	μА	VDD = 3.0V		
	Δ IVREF	VREF Current (Note 5)	-		300	μΑ	VDD = 3.0V		

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
 - The test conditions for all IDD measurements in active operation mode are:
 - $\underline{\mathsf{OSC1}} \mathtt{=} \mathsf{external} \ \mathsf{square} \ \mathsf{wave}, \ \mathsf{from} \ \mathsf{rail} \ \mathsf{to} \ \mathsf{rail}; \ \mathsf{all} \ \mathsf{I/O} \ \mathsf{pins} \ \mathsf{tristated}, \ \mathsf{pulled} \ \mathsf{to} \ \mathsf{Vdd},$
 - MCLR = VDD; WDT enabled/disabled as specified.
 - 3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD to Vss.
 - 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in $k\Omega$.
 - 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.3 DC CHARACTERISTICS: PIC16C62XA/CR62XA-04 (Commercial, Industrial, Extended) PIC16C62XA/CR62XA-20 (Commercial, Industrial, Extended)

PIC16LC62XA/LCR62XA-04 (Commercial, Industrial) PIC16LC62XA/LCR62XA-20 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated)						
		Operating temperature -40°C	≤ TA ≤	+85°C	for inc	dustrial	and	
		0°C		≤ TA ≤ +70°C for commercial and				
		−40°C	_ ≤ Ta ≤	+125°(C for e	xtende	<u> </u>	
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
D001 D001A	VDD	Supply Voltage	3.0 4.5	-	5.5 5.5	V V	XT, RC and LP osc configuration HS osc configuration	
D002	VDR	RAM Data Retention Voltage (Note 1)	-	1.5*	_	V	Device in SLEEP mode	
D003	VPOR	VDD start voltage to ensure Power-on Reset	-	Vss	_	V	See section on power-on reset for details	
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	_	_	V/ms	See section on power-on reset for details	
D005	VBOR	Brown-out Detect Voltage	3.7 3.7	4.0 4.0	4.3 4.4	V	BOREN configuration bit is cleared (Extended)	
D010	IDD	Supply Current (Note 2)	_	1.2	2.0	mA	XT and RC osc configuration Fosc = 4 MHz, VDD = 5.5V, WDT disabled (Note 4)	
D010A			_	35	70	μΑ	LP osc configuration, PIC16C62XA-04 only FOSC = 32 kHz, VDD = 4.0V, WDT disabled HS osc configuration	
D013			-	3.0	7.5	mA	Fosc = 20 MHz, VDD = 5.5V, WDT disabled	
D020	IPD	Power Down Current (Note 3)	_	1.0	2.5 15	μA μA	VDD=4.0V, WDT disabled (125°C)	
	ΔIWDT	WDT Current (Note 5)	_	6.0	10 12	μA μA	VDD=4.0V (125°C)	
D023	ΔIBOR	Brown-out Reset Current (Note 5)	_	75	150	μA	BOR enabled, VDD = 5.0V	
	ΔІСОМР	Comparator Current for each Comparator (Note 5)	_	60	75	μΑ	VDD = 4.0V	
	Δ IVREF	VREF Current (Note 5)	_	90	200	μΑ	VDD = 4.0V	

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
 - The test conditions for all IDD measurements in active operation mode are:
 - OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
 - MCLR = VDD; WDT enabled/disabled as specified.
 - 3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.
 - 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in $k\Omega$.
 - 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.4 DC CHARACTERISTICS: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)

Operating temperature $-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C}$ for industrial and

 $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial and $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended

Operating voltage VDD range as described in DC spec Table 12-1 and Table 12-2

		Operating voltage VDD range as described in DC spec Table 12-1 and Table 12-2					2-2
Param. No.	Sym	Characteristic	Min	Тур†	Max	Unit	Conditions
	VIL	Input Low Voltage					
		I/O ports					
D030		with TTL buffer	Vss	_	0.8V	V	VDD = 4.5V to 5.5V
					0.15VDD		otherwise
D031		with Schmitt Trigger input	Vss		0.2Vdd	V	
D032		MCLR, RA4/T0CKI,OSC1 (in RC	Vss	-	0.2Vdd	V	Note1
		mode)					
D033		OSC1 (in XT and HS)	Vss	-	0.3Vdd	V	
		OSC1 (in LP)	Vss	-	0.6VDD-1.0	V	
	VIH	Input High Voltage					
		I/O ports		-			
D040		with TTL buffer	2.0V	-	VDD	V	VDD = 4.5V to 5.5V
			.25VDD + 0.8V		VDD		otherwise
D041		with Schmitt Trigger input	0.8VDD		VDD		
D042		MCLR RA4/T0CKI	0.8VDD	-	VDD	V	
D043		OSC1 (XT, HS and LP)	0.7VDD	-	VDD	V	
D043A		OSC1 (in RC mode)	0.9VDD	000	400		Note1
D070	IPURB	PORTB weak pull-up current	50	200	400	μΑ	VDD = 5.0V, VPIN = VSS
	l IIL	Input Leakage Current (Notes 2, 3)					
	"L	I/O ports (Except PORTA)			±1.0	пΔ	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	_	_	±0.5	μΑ	· · · · ·
D061		RA4/T0CKI	_	_	±1.0	μΑ	· · · ·
D063		OSC1, MCLR	_	_	±5.0	•	Vss ≤ Vpin ≤ VDD, XT, HS and LP osc
						,	configuration
	Vol	Output Low Voltage					
D080		I/O ports	-	-	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to +85°C
			-	-	0.6	V	IOL=7.0 mA, VDD=4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	-	-	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to +85°C
			-	-	0.6	V	IOL=1.2 mA, VDD=4.5V, +125°C
	Voн	Output High Voltage (Note 3)					
D090		I/O ports (Except RA4)	VDD-0.7	-	-	V	IOH=-3.0 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	-	-	V	IOH=-2.5 mA, VDD=4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	-	-	V	IOH=-1.3 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	-	-	V	IOH=-1.0 mA, VDD=4.5V, +125°C
*		Open-Drain High Voltage			10*	V	RA4 pin PIC16C62X, PIC16LC62X
	Vod				10*		RA4 pin PIC16C62XA, PICLC62XA,
							CR62XA, LCR62XA
		Capacitive Loading Specs on					
D400	00000	Output Pins			4.5		NT 110 and 1 D and 1 and
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	Cio	All I/O pins/OSC2 (in RC mode)			50	рF	CHOCK USED TO DITIVE OSC 1.
וטוע		All I/O pins/OSC2 (in RC mode)] 30	PΓ	

^{*} These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

^{2:} The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

^{3:} Negative current is defined as coming out of the pin.

TABLE 12-2: COMPARATOR SPECIFICATIONS

Operating Conditions: Vdd range as described in Table 12-1, -40°C<TA<+125°C. Current consumption is specified in Table 12-1.

Characteristics	Sym	Min	Тур	Max	Units	Comments
Input offset voltage			± 5.0	± 10	mV	
Input common mode voltage		0		VDD - 1.5	V	
CMRR		+55*			db	
Response Time ⁽¹⁾			150*	400* 600*	ns ns	PIC16C62X(A) PIC16LC62X
Comparator Mode Change to Output Valid				10*	μs	

^{*} These parameters are characterized but not tested.

TABLE 12-3: VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions:Vdd range as described in Table 12-1, -40°C<TA<+125°C. Current consumption is specified in Table 12-1.

Characteristics	Sym	Min	Тур	Max	Units	Comments
Resolution		VDD/24		VDD/32	LSB	
Absolute Accuracy				±1/4 ±1/2	LSB LSB	Low Range (VRR=1) High Range (VRR=0)
Unit Resistor Value (R)			2K*		Ω	Figure 8-2
Settling Time ⁽¹⁾				10*	μs	

^{*} These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at $(V_{DD} - 1.5)/2$ while the other input transitions from V_{SS} to V_{DD} .

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from 0000 to 1111.

12.5 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

Т			
F	Frequency	Т Т	Time
		-	

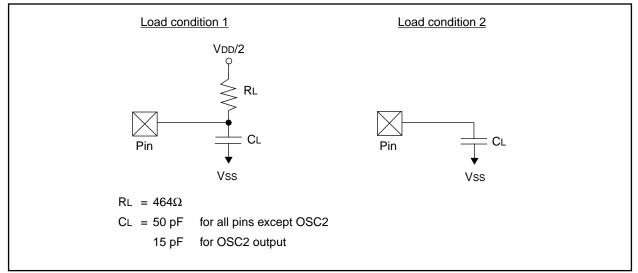
Lowercase subscripts (pp) and their meanings:

Lowerdas	e subscripts (pp) and their meanings.		
рр			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	MCLR		

Uppercase letters and their meanings:

S			
F	Fall	P	Period
Н	High	R	Rise
1	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-1: LOAD CONDITIONS



12.6 <u>Timing Diagrams and Specifications</u>

FIGURE 12-2: EXTERNAL CLOCK TIMING

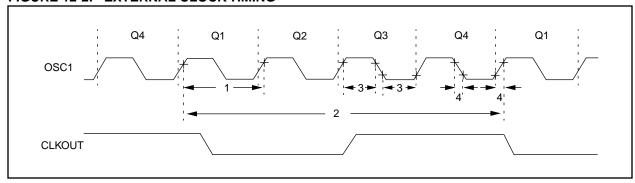


TABLE 12-4: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fos	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode, VDD=5.0V
		(Note 1)	DC	_	20	MHz	HS osc mode
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode, VDD=5.0V
		(Note 1)	0.1	_	4	MHz	XT osc mode
			1	_	20	MHz	HS osc mode
			DC	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	50	_	_	ns	HS osc mode
			5	_	_	μs	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			50	_	1,000	ns	HS osc mode
			5	_	_	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	1.0	Fosc/4	DC	μs	Tcys=Fosc/4
3*	TosL,	External Clock in (OSC1) High or	100*	_	_	ns	XT oscillator, Tosc L/H duty cycle
	TosH	Low Time	2*	_	_	μs	LP oscillator, Tosc L/H duty cycle
			20*	_	_	ns	HS oscillator, Tosc L/H duty
							cycle
4*	TosR,	External Clock in (OSC1) Rise or	25*	_	–	ns	XT oscillator
	TosF	Fall Time	50*	_	—	ns	LP oscillator
			15*			ns	HS oscillator

^{*} These parameters are characterized but not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-3: CLKOUT AND I/O TIMING

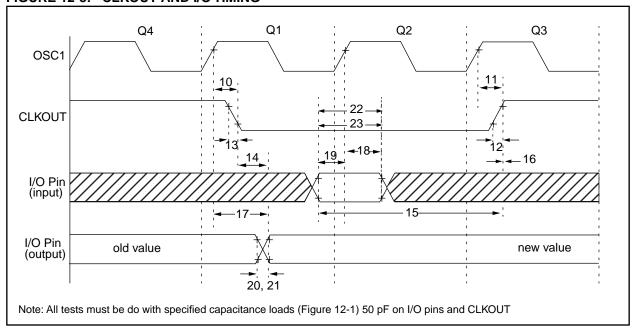


TABLE 12-5: **CLKOUT AND I/O TIMING REQUIREMENTS**

Parameter #	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓ (1)		75 —	200 400	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
11*	TosH2ckH	OSC1↑ to CLKOUT↑ (1)		75 —	200 400	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
12*	TckR	CLKOUT rise time (1)	_ _	35 —	100 200	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
13*	TckF	CLKOUT fall time (1)		35 —	100 200	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
14*	TckL2ioV	CLKOUT ↓ to Port out valid ⁽¹⁾		_	20	ns	
15*	TioV2ckH	Port in valid before CLKOUT ↑ ⁽¹⁾	Tosc +200 ns Tosc +400 ns	_	_	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
16*	TckH2ioI	Port in hold after CLKOUT ↑ (1)	0	_	_	ns	
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		50	150 300	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	100 200	_	_	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	_	_	ns	
20*	TioR	Port output rise time		10 —	40 80	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
21*	TioF	Port output fall time	- -	10 —	40 80	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
22*	Tinp	RB0/INT pin high or low time	25 40			ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
23	Trbp	RB<7:4> change interrupt high or low time	Tcy	_	_	ns	

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^{*} These parameters are characterized but not tested
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc

FIGURE 12-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

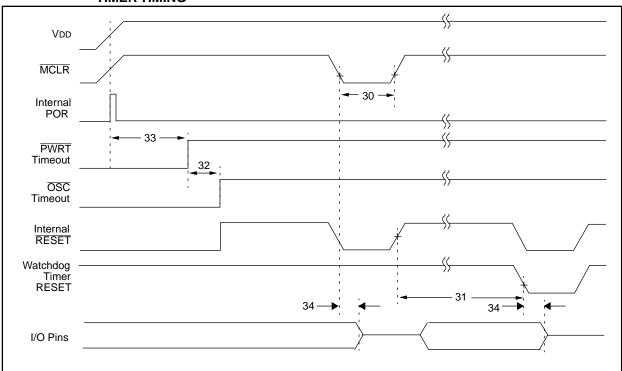


FIGURE 12-5: BROWN-OUT RESETTIMING

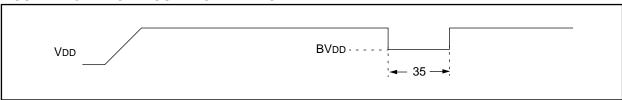


TABLE 12-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2000	_	_	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	$VDD = 5.0V, -40^{\circ} \text{ to } +85^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc	_	_	Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	$VDD = 5.0V, -40^{\circ} \text{ to } +85^{\circ}C$
34	Tıoz	I/O hi-impedance from MCLR low		_	2.0	μs	
35	TBOR	Brown-out Reset Pulse Width	100*	_	_	μs	$3.7V \le VDD \le 4.3V$

^{*} These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-6: TIMERO CLOCK TIMING

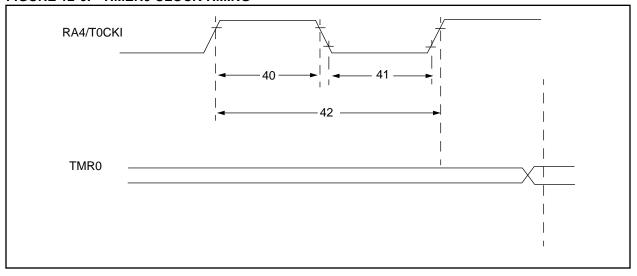
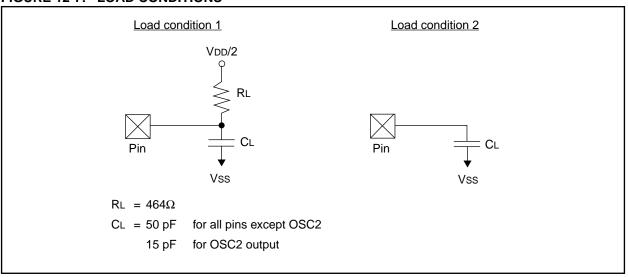


TABLE 12-7: TIMERO CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 Tcy + 20*	_	_	ns	
			With Prescaler	10*	_	_	ns	
41	TtOL	T0CKI Low Pulse Width	No Prescaler	0.5 Tcy + 20*	_	_	ns	
			With Prescaler	10*	_	_	ns	
42	Tt0P	T0CKI Period		Tcy + 40* N			ns	N = prescale value (1, 2, 4,, 256)

^{*} These parameters are characterized but not tested.

FIGURE 12-7: LOAD CONDITIONS



[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NOTES:

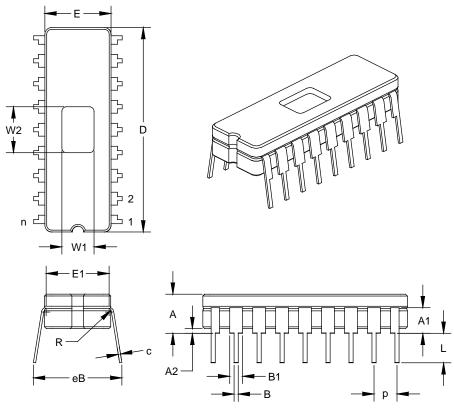
13.0 DEVICE CHARACTERIZATION INFORMATION

Not Available at this time.

NOTES:

14.0 PACKAGING INFORMATION

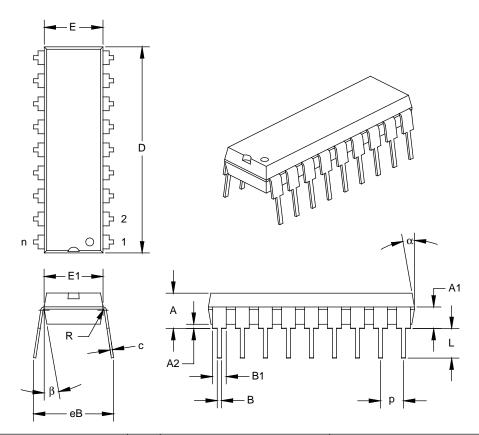
Package Type: K04-010 18-Lead Ceramic Dual In-line with Window (JW) – 300 mil



Units			INCHES*		М	ILLIMETER	S
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
PCB Row Spacing			0.300			7.62	
Number of Pins	n		18			18	
Pitch	р	0.098	0.100	0.102	2.49	2.54	2.59
Lower Lead Width	В	0.016	0.019	0.021	0.41	0.47	0.53
Upper Lead Width	B1	0.050	0.055	0.060	1.27	1.40	1.52
Shoulder Radius	R	0.010	0.013	0.015	0.25	0.32	0.38
Lead Thickness	С	0.008	0.010	0.012	0.20	0.25	0.30
Top to Seating Plane	Α	0.175	0.183	0.190	4.45	4.64	4.83
Top of Lead to Seating Plane	A1	0.091	0.111	0.131	2.31	2.82	3.33
Base to Seating Plane	A2	0.015	0.023	0.030	0.00	0.57	0.76
Tip to Seating Plane	L	0.125	0.138	0.150	3.18	3.49	3.81
Package Length	D	0.880	0.900	0.920	22.35	22.86	23.37
Package Width	E	0.285	0.298	0.310	7.24	7.56	7.87
Radius to Radius Width	E1	0.255	0.270	0.285	6.48	6.86	7.24
Overall Row Spacing	eВ	0.345	0.385	0.425	8.76	9.78	10.80
Window Width	W1	0.130	0.140	0.150	0.13	0.14	0.15
Window Length	W2	0.190	0.200	0.210	0.19	0.2	0.21

^{*} Controlling Parameter.

Package Type: K04-007 18-Lead Plastic Dual In-line (P) - 300 mil



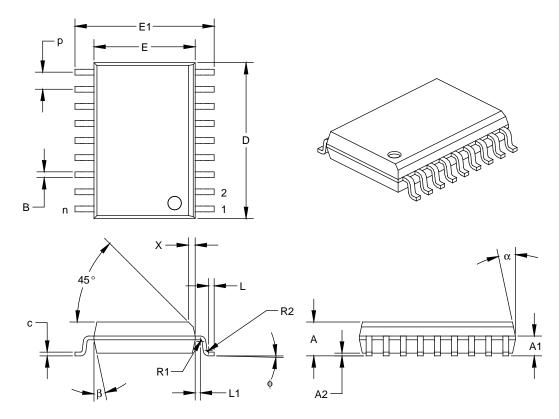
Units			INCHES*		M	ILLIMETER:	S
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
PCB Row Spacing			0.300			7.62	
Number of Pins	n		18			18	
Pitch	р		0.100			2.54	
Lower Lead Width	В	0.013	0.018	0.023	0.33	0.46	0.58
Upper Lead Width	B1 [†]	0.055	0.060	0.065	1.40	1.52	1.65
Shoulder Radius	R	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	С	0.005	0.010	0.015	0.13	0.25	0.38
Top to Seating Plane	Α	0.110	0.155	0.155	2.79	3.94	3.94
Top of Lead to Seating Plane	A1	0.075	0.095	0.115	1.91	2.41	2.92
Base to Seating Plane	A2	0.000	0.020	0.020	0.00	0.51	0.51
Tip to Seating Plane	L	0.125	0.130	0.135	3.18	3.30	3.43
Package Length	D [‡]	0.890	0.895	0.900	22.61	22.73	22.86
Molded Package Width	E [‡]	0.245	0.255	0.265	6.22	6.48	6.73
Radius to Radius Width	E1	0.230	0.250	0.270	5.84	6.35	6.86
Overall Row Spacing	еВ	0.310	0.349	0.387	7.87	8.85	9.83
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

^{*} Controlling Parameter.

[†] Dimension "B1" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B1."

[‡] Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

Package Type: K04-051 18-Lead Plastic Small Outline (SO) - Wide, 300 mil



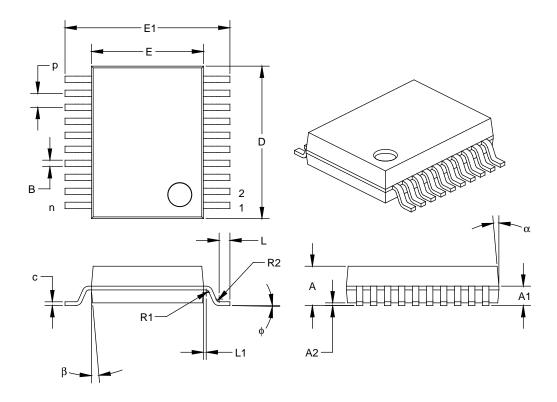
Units			INCHES*		М	ILLIMETERS	3
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	р		0.050			1.27	
Number of Pins	n		18			18	
Overall Pack. Height	Α	0.093	0.099	0.104	2.36	2.50	2.64
Shoulder Height	A1	0.048	0.058	0.068	1.22	1.47	1.73
Standoff	A2	0.004	0.008	0.011	0.10	0.19	0.28
Molded Package Length	D [‡]	0.450	0.456	0.462	11.43	11.58	11.73
Molded Package Width	E [‡]	0.292	0.296	0.299	7.42	7.51	7.59
Outside Dimension	E1	0.394	0.407	0.419	10.01	10.33	10.64
Chamfer Distance	X	0.010	0.020	0.029	0.25	0.50	0.74
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.011	0.016	0.021	0.28	0.41	0.53
Foot Angle	φ	0	4	8	0	4	8
Radius Centerline	L1	0.010	0.015	0.020	0.25	0.38	0.51
Lead Thickness	С	0.009	0.011	0.012	0.23	0.27	0.30
Lower Lead Width	B [†]	0.014	0.017	0.019	0.36	0.42	0.48
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

^{*} Controlling Parameter.

[†] Dimension "B" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B."

[‡] Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

Package Type: K04-072 20-Lead Plastic Shrink Small Outine (SS) - 5.30 mm



Units			INCHES		М	ILLIMETERS	S*
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	р		0.026			0.65	
Number of Pins	n		20			20	
Overall Pack. Height	Α	0.068	0.073	0.078	1.73	1.86	1.99
Shoulder Height	A1	0.026	0.036	0.046	0.66	0.91	1.17
Standoff	A2	0.002	0.005	0.008	0.05	0.13	0.21
Molded Package Length	D [‡]	0.278	0.283	0.289	7.07	7.20	7.33
Molded Package Width	E [‡]	0.205	0.208	0.212	5.20	5.29	5.38
Outside Dimension	E1	0.301	0.306	0.311	7.65	7.78	7.90
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.015	0.020	0.025	0.38	0.51	0.64
Foot Angle	φ	0	4	8	0	4	8
Radius Centerline	L1	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	С	0.005	0.007	0.009	0.13	0.18	0.22
Lower Lead Width	Β [†]	0.010	0.012	0.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

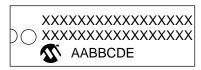
^{*} Controlling Parameter.

[†] Dimension "B" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B."

[‡] Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

14.1 Package Marking Information

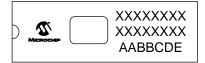
18-Lead PDIP



18-Lead SOIC (.300")



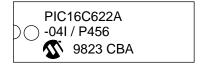
18-Lead CERDIP Windowed



20-Lead SSOP



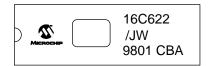
Example



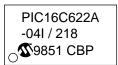
Example



Example



Example



Legen	d: MMM	Microchip part number information
	XXX	Customer specific information*
	AA	Year code (last 2 digits of calendar year)
	BB	Week code (week of January 1 is week '01')
	С	Facility code of the plant at which wafer is manufactured
		O = Outside Vendor
		C = 5" Line
		S = 6" Line
		H = 8" Line
	D	Mask revision number
	Е	Assembly code of the plant or country of origin in which
		part was assembled
Note:	In the eve	nt the full Microchip part number cannot be marked on one line, it will

be carried over to the next line thus limiting the number of available characters for customer specific information.

Standard OTP marking consists of Microchip part number, year code, week code, facility code.

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask rev#, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

NOTES:

APPENDIX A: ENHANCEMENTS

The following are the list of enhancements over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14 bits.
 This allows larger page sizes both in program memory (4K now as opposed to 512 before) and register file (up to 128 bytes now versus 32 bytes before).
- A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
- Data memory paging is slightly redefined. STATUS register is modified.
- 4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.

 Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
- OPTION and TRIS registers are made addressable.
- Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- Wake up from SLEEP through interrupt is added.
- Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. Timer0 clock input, T0CKI pin is also a port pin (RA4/T0CKI) and has a TRIS bit.
- 14. FSR is made a full 8-bit register.
- "In-circuit programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, /VPP, RB6 (clock) and RB7 (data in/out).
- 16. PCON status register is added with a Power-on-Reset (POR) status bit and a Brown-out Reset status bit (BOR).
- Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- 18. PORTA inputs are now Schmitt Trigger inputs.
- 19. Brown-out Reset reset has been added.
- Common RAM registers F0h-FFh implemented in bank1.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change reset vector to 0000h.

APPENDIX C: WHAT'S NEW

The format of certain sections of this data sheet have been changed to be consistent with other product families

 PORTB input buffers have changed to TTL from Schmitt Trigger.

APPENDIX D: WHAT'S CHANGED

- Table 3-1 was changed to reflect the TTL input buffers on PORTB.
- 2. Figure 5-5 and Figure 5-6 were updated to reflect the TTL input buffers on PORTB.
- 3. Figure 9-7 was updated.
- The orientation of the diode in Figure 9-19 was changed.
- A device specification for JW devices was added to Table 12-1.
- 6. Max spec for Brown-out Reset current was changed to 15 μA in Section 12.1 and Section 12.2.
- Information added to support the 2.5V "LC" devices.
- 8. Information added to support the "A" version of the devices.

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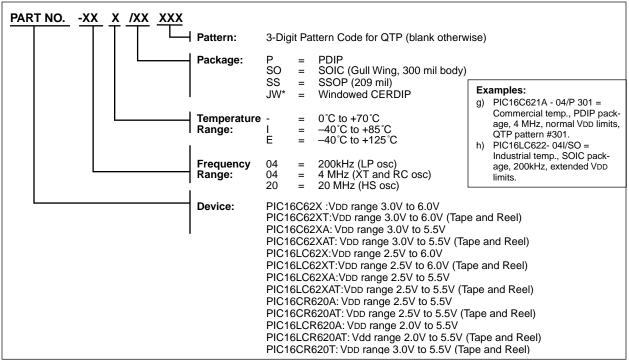
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^{*} JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type (including LC devices).

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